

# PIC12C5XX

### 8-Pin, 8-Bit CMOS Microcontroller

#### Devices included in this Data Sheet:

PIC12C508 and PIC12C509 are 8-bit microcontrollers packaged in 8-lead packages. They are based on the Enhanced PIC16C5X family.

#### High-Performance RISC CPU:

- Only 33 single word instructions to learn
- All instructions are single cycle (1 µs) except for program branches which are two-cycle
- Operating speed: DC 4 MHz clock input DC 1  $\mu s$  instruction cycle

Device	EPROM	RAM
PIC12C508	512 x 12	25
PIC12C509	1024 x 12	41

- · 12-bit wide instructions
- · 8-bit wide data path
- Seven special function hardware registers
- Two-level deep hardware stack
- Direct, indirect and relative addressing modes for data and instructions
- Internal 4 MHz RC oscillator with programmable calibration
- In-circuit serial programming

#### **Peripheral Features:**

- 8-bit real time clock/counter (TMR0) with 8-bit programmable prescaler
- Power-On Reset (POR)
- Device Reset Timer (DRT)
- Watchdog Timer (WDT) with its own on-chip RC oscillator for reliable operation
- Programmable code-protection
- · Power saving SLEEP mode
- Wake-up from SLEEP on pin change
- · Internal weak pull-ups on I/O pins
- Internal pull-up on MCLR pin
- · Selectable oscillator options:
  - INTRC: Internal 4 MHz RC oscillator
  - EXTRC: External low-cost RC oscillator
  - XT: Standard crystal/resonator
  - LP: Power saving, low frequency crystal

## technologyFully static design

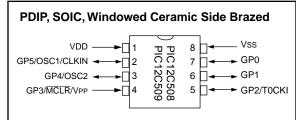
**CMOS Technology:** 

• Wide operating voltage range:

Low power, high speed CMOS EPROM

- Commercial: 2.5V to 5.5V
- Industrial: 2.5V to 5.5V
- Extended: 3.0V to 5.5V
- Low power consumption
  - < 2 mA @ 5V, 4 MHz
  - 15 μA typical @ 3V, 32 KHz
  - < 1 µA typical standby current

#### Pin Diagram





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#### 1.0 GENERAL DESCRIPTION

The PIC12C5XX from Microchip Technology is a family of low-cost, high performance, 8-bit, fully static, EPROM/ROM-based CMOS microcontrollers. It employs a RISC architecture with only 33 single word/ single cycle instructions. All instructions are single cycle (1  $\mu$ s) except for program branches which take two cycles. The PIC12C5XX delivers performance an order of magnitude higher than its competitors in the same price category. The 12-bit wide instructions are highly symmetrical resulting in 2:1 code compression over other 8-bit microcontrollers in its class. The easy to use and easy to remember instruction set reduces development time significantly.

The PIC12C5XX products are equipped with special features that reduce system cost and power requirements. The Power-On Reset (POR) and Device Reset Timer (DRT) eliminate the need for external reset circuitry. There are four oscillator configurations to choose from, including INTRC internal oscillator mode and the power-saving LP (Low Power) oscillator. Power saving SLEEP mode, Watchdog Timer and code protection features improve system cost, power and reliability.

The PIC12C5XX are available in the cost-effective One-Time-Programmable (OTP) versions which are suitable for production in any volume. The customer can take full advantage of Microchip's price leadership in OTP microcontrollers while benefiting from the OTP's flexibility.

The PIC12C5XX products are supported by a full-featured macro assembler, a software simulator, an in-circuit emulator, a 'C' compiler, fuzzy logic support tools, a low-cost development programmer, and a full featured programmer. All the tools are supported on IBM<sup>®</sup> PC and compatible machines.

#### 1.1 <u>Applications</u>

The PIC12C5XX series fits perfectly in applications ranging from personal care appliances and security systems to low-power remote transmitters/receivers. The EPROM technology makes customizing application programs (transmitter codes, appliance settings, receiver frequencies, etc.) extremely fast and convenient. The small footprint packages, for through hole or surface mounting, make this microcontroller series perfect for applications with space limitations. Low-cost, low-power, high performance, ease of use and I/O flexibility make the PIC12C5XX series very versatile even in areas where no microcontroller use has been considered before (e.g., timer functions, replacement of "glue" logic and PLD's in larger systems, coprocessor applications).



#### TABLE 1-1: PIC12C5XX FAMILY OF DEVICES

		PIC12C508	PIC12C509	
Clock	Maximum Frequency of Operation (MHz)	4	4	
Memory	EPROM Program Memory (x12 words)	512	1024	
	Data Memory (bytes)	25	41	
Peripherals	Timer Module(s)	TMR0	TMR0	
	Wake-up from SLEEP on pin change	Yes	Yes	
	I/O Pins	5	5	
	Input Pins	1	1	
	Internal Pull-ups	Yes	Yes	
Features	Voltage Range (Volts)	2.5-5.5	2.5-5.5	
	In-Circuit Serial Programming	Yes	Yes	
	Number of Instructions	33	33	
	Packages	8-pin DIP, SOIC	8-pin DIP, SOIC	

All PIC12C5XX devices have Power-on Reset, selectable Watchdog Timer, selectable code protect and high I/O current capability. All PIC12C5XX devices use serial programming with data pin GP1 and clock pin GP0.



#### 2.0 PIC12C5XX DEVICE VARIETIES

A variety of packaging options are available. Depending on application and production requirements, the proper device option can be selected using the information in this section. When placing orders, please use the PIC12C5XX Product Identification System at the back of this data sheet to specify the correct part number.

#### 2.1 <u>UV Erasable Devices</u>

The UV erasable version, offered in ceramic side brazed package, is optimal for prototype development and pilot programs.

The UV erasable version can be erased and reprogrammed to any of the configuration modes.

Note:	Please note that erasing the device will also erase the pre-programmed internal calibration value for the internal oscillator. The calibration value must be saved prior
	to erasing the part.

Microchip's PICSTART<sup>®</sup> PLUS and PRO MATE<sup>™</sup> programmers all support programming of the PIC12C5XX. Third party programmers also are available; refer to the *Microchip Third Party Guide* for a list of sources.

#### 2.2 <u>One-Time-Programmable (OTP)</u> <u>Devices</u>

The availability of OTP devices is especially useful for customers who need the flexibility for frequent code updates or small volume applications.

The OTP devices, packaged in plastic packages permit the user to program them once. In addition to the program memory, the configuration bits must also be programmed.

#### 2.3 <u>Quick-Turnaround-Production (QTP)</u> <u>Devices</u>

Microchip offers a QTP Programming Service for factory production orders. This service is made available for users who choose not to program a medium to high quantity of units and whose code patterns have stabilized. The devices are identical to the OTP devices but with all EPROM locations and fuse options already programmed by the factory. Certain code and prototype verification procedures do apply before production shipments are available. Please contact your local Microchip Technology sales office for more details.

#### 2.4 <u>Serialized Quick-Turnaround</u> <u>Production (SQTP<sup>SM</sup>) Devices</u>

Microchip offers a unique programming service where a few user-defined locations in each device are programmed with different serial numbers. The serial numbers may be random, pseudo-random or sequential.

Serial programming allows each device to have a unique number which can serve as an entry-code, password or ID number.



# PIC12C5XX

NOTES:



#### 3.0 ARCHITECTURAL OVERVIEW

The high performance of the PIC12C5XX family can be attributed to a number of architectural features commonly found in RISC microprocessors. To begin with, the PIC12C5XX uses a Harvard architecture in which program and data are accessed on separate buses. This improves bandwidth over traditional von Neumann architecture where program and data are fetched on the same bus. Separating program and data memory further allows instructions to be sized differently than the 8-bit wide data word. Instruction opcodes are 12-bits wide making it possible to have all single word instructions. A 12-bit wide program memory access bus fetches a 12-bit instruction in a single cycle. A two-stage pipeline overlaps fetch and execution of instructions. Consequently, all instructions (33) execute in a single cycle (1µs @ 4MHz) except for program branches.

The PIC12C508 address 512 x 12 of program memory, the PIC12C509 addresses 1K x 12 of program memory. All program memory is internal.

The PIC12C5XX can directly or indirectly address its register files and data memory. All special function registers including the program counter are mapped in the data memory. The PIC12C5XX has a highly orthogonal (symmetrical) instruction set that makes it possible to carry out any operation on any register using any addressing mode. This symmetrical nature and lack of 'special optimal situations' make programming with the PIC12C5XX simple yet efficient. In addition, the learning curve is reduced significantly.

The PIC12C5XX device contains an 8-bit ALU and working register. The ALU is a general purpose arithmetic unit. It performs arithmetic and Boolean functions between data in the working register and any register file.

The ALU is 8-bits wide and capable of addition, subtraction, shift and logical operations. Unless otherwise mentioned, arithmetic operations are two's complement in nature. In two-operand instructions, typically one operand is the W (working) register. The other operand is either a file register or an immediate constant. In single operand instructions, the operand is either the W register or a file register.

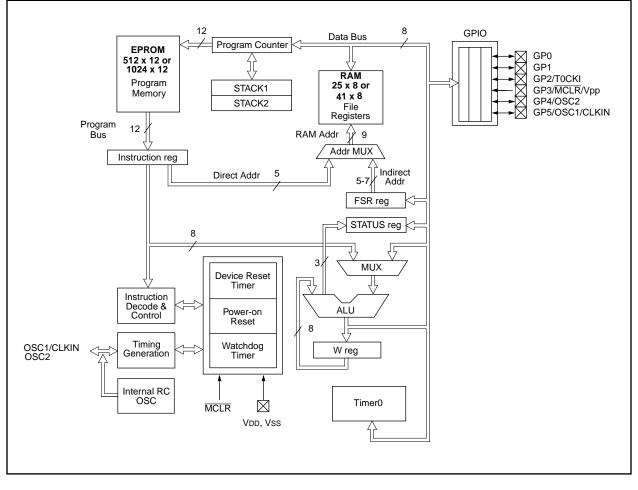
The W register is an 8-bit working register used for ALU operations. It is not an addressable register.

Depending on the instruction executed, the ALU may affect the values of the Carry (C), Digit Carry (DC), and Zero (Z) bits in the STATUS register. The C and DC bits operate as a borrow and digit borrow out bit, respectively, in subtraction. See the SUBWF and ADDWF instructions for examples.

A simplified block diagram is shown in Figure 3-1, with the corresponding device pins described in Table 3-1.



#### FIGURE 3-1: PIC12C5XX BLOCK DIAGRAM





Name	DIP Pin #	SOIC Pin #	I/O/P Type	Buffer Type	Description
GP0	7	7	I/O	TTL/ST	Bi-directional I/O port/ serial programming data. Can be software programmed for internal weak pull-up and wake-up from SLEEP on pin change. This buffer is a Schmitt Trigger input when used in serial programming mode.
GP1	6	6	I/O	TTL/ST	Bi-directional I/O port/ serial programming clock. Can be software programmed for internal weak pull-up and wake-up from SLEEP on pin change. This buffer is a Schmitt Trigger input when used in serial programming mode.
GP2/T0CKI	5	5	I/O	ST	Bi-directional I/O port. Can be configured as T0CKI.
GP3/MCLR/Vpp	4	4	I	TTL	Input port/master clear (reset) input/programming volt- age input. When configured as MCLR, this pin is an active low reset to the device. Voltage on MCLR/VPP must not exceed VDD during normal device operation. Can be software programmed for internal weak pull-up and wake-up from SLEEP on pin change. Weak pull- up always on if configured as MCLR
GP4/OSC2	3	3	I/O	TTL	Bi-directional I/O port/oscillator crystal output. Con- nections to crystal or resonator in crystal oscillator mode (XT and LP modes only, GPIO in other modes).
GP5/OSC1/CLKIN	2	2	I/O	TTL/ST	Bidirectional IO port/oscillator crystal input/external clock source input (GPIO in Internal RC mode only, OSC1 in all other oscillator modes). TTL input when GPIO, ST input in external RC oscillator mode.
Vdd	1	1	Р	_	Positive supply for logic and I/O pins
Vss	8	8	Р		Ground reference for logic and I/O pins

Legend: I = input, O = output, I/O = input/output, P = power, — = not used, TTL = TTL input, ST = Schmitt Trigger input



#### 3.1 Clocking Scheme/Instruction Cycle

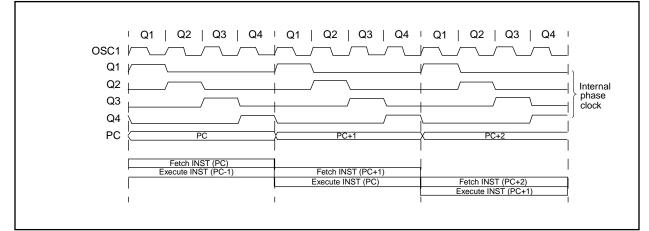
The clock input (OSC1/CLKIN pin) is internally divided by four to generate four non-overlapping quadrature clocks namely Q1, Q2, Q3 and Q4. Internally, the program counter is incremented every Q1, and the instruction is fetched from program memory and latched into instruction register in Q4. It is decoded and executed during the following Q1 through Q4. The clocks and instruction execution flow is shown in Figure 3-2 and Example 3-1.

#### 3.2 Instruction Flow/Pipelining

An Instruction Cycle consists of four Q cycles (Q1, Q2, Q3 and Q4). The instruction fetch and execute are pipelined such that fetch takes one instruction cycle while decode and execute takes another instruction cycle. However, due to the pipelining, each instruction effectively executes in one cycle. If an instruction causes the program counter to change (e.g., GOTO) then two cycles are required to complete the instruction (Example 3-1).

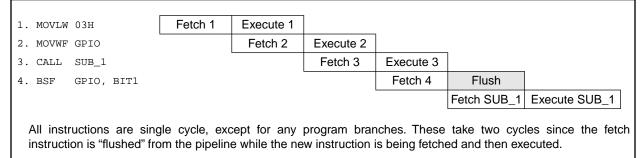
A fetch cycle begins with the program counter (PC) incrementing in Q1.

In the execution cycle, the fetched instruction is latched into the Instruction Register (IR) in cycle Q1. This instruction is then decoded and executed during the Q2, Q3, and Q4 cycles. Data memory is read during Q2 (operand read) and written during Q4 (destination write).



#### FIGURE 3-2: CLOCK/INSTRUCTION CYCLE

#### EXAMPLE 3-1: INSTRUCTION PIPELINE FLOW





#### 4.0 MEMORY ORGANIZATION

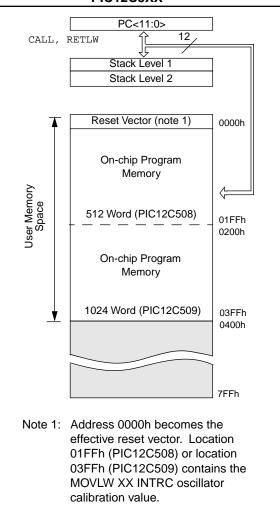
PIC12C5XX memory is organized into program memory and data memory. For devices with more than 512 bytes of program memory, a paging scheme is used. Program memory pages are accessed using one STA-TUS register bit. For the PIC12C509 with a data memory register file of more than 32 registers, a banking scheme is used. Data memory banks are accessed using the File Select Register (FSR).

#### 4.1 Program Memory Organization

The PIC12C508 and PIC12C509 each have a 12-bit Program Counter (PC) capable of addressing a 2K x 12 program memory space.

Only the first 512 x 12 (0000h-01FFh) for the PIC12C508 and 1K x 12 (0000h-03FFh) for the PIC12C509 are physically implemented. Refer to Figure 4-1. Accessing a location above these boundaries will cause a wrap-around within the first 512 x 12 space (PIC12C508) or 1K x 12 space (PIC12C509). The effective reset vector is at 000h, (see Figure 4-1). Location 01FFh (PIC12C508) or location 03FFh (PIC12C509) contains the internal clock oscillator calibration value. This value should never be overwritten.

#### FIGURE 4-1: PROGRAM MEMORY MAP AND STACK FOR THE PIC12C5XX





#### 4.2 Data Memory Organization

Data memory is composed of registers, or bytes of RAM. Therefore, data memory for a device is specified by its register file. The register file is divided into two functional groups: special function registers and general purpose registers.

The special function registers include the TMR0 register, the Program Counter (PC), the Status Register, the I/O registers (ports), and the File Select Register (FSR). In addition, special purpose registers are used to control the I/O port configuration and prescaler options.

The general purpose registers are used for data and control information under command of the instructions.

For the PIC12C508, the register file is composed of 7 special function registers and 25 general purpose registers (Figure 4-2).

For the PIC12C509, the register file is composed of 7 special function registers, 25 general purpose registers, and 16 general purpose registers that may be addressed using a banking scheme (Figure 4-3).

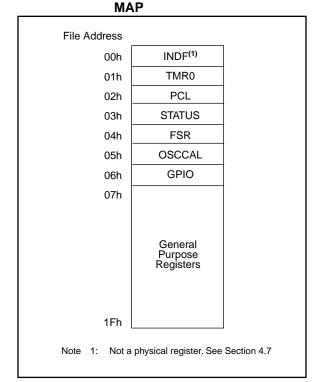
#### 4.2.1 GENERAL PURPOSE REGISTER FILE

The general purpose register file is accessed either directly or indirectly through the file select register FSR (Section 4.7).

#### FSR<6:5>-01 00 File Address INDF<sup>(1)</sup> 20h 00h TMR0 01h PCL 02h Addresses map STATUS 03h back to FSR 04h addresses in Bank 0. OSCCAL 05h GPIO 06h 07h General Purpose Registers 2Fh 0Fh 10h 30h General General Purpose Purpose Registers Registers 1Fh 3Fh Bank 0 Bank 1 Note 1: Not a physical register. See Section 4.7 *www.sameleo*

#### FIGURE 4-3: PIC12C509 REGISTER FILE MAP

### FIGURE 4-2: PIC12C508 REGISTER FILE



#### 4.2.2 SPECIAL FUNCTION REGISTERS

The Special Function Registers (SFRs) are registers used by the CPU and peripheral functions to control the operation of the device (Table 4-1). The special registers can be classified into two sets. The special function registers associated with the "core" functions are described in this section. Those related to the operation of the peripheral features are described in the section for each peripheral feature.

#### TABLE 4-1:SPECIAL FUNCTION REGISTER (SFR) SUMMARY

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-On Reset	Value on MCLR and WDT Reset	Value on Wake-up on Pin Change
N/A	TRIS	I/O control	l register	S						11 1111	11 1111	11 1111
N/A	OPTION	Contains of prescaler,			0			NDT		1111 1111	1111 1111	1111 1111
00h	INDF	Uses conto register)	ents of F	SR to a	ddress c	lata me	mory (n	ot a phy	/sical	xxxx xxxx	uuuu uuuu	uuuu uuuu
01h	TMR0	8-bit real-t	ime cloc	k/counte	er					XXXX XXXX	uuuu uuuu	uuuu uuuu
02h <sup>(1)</sup>	PCL	Low order	8 bits of	PC						1111 1111	1111 1111	1111 1111
03h	STATUS	GPWUF	_	PA0	TO	PD	Z	DC	С	0001 1xxx	000q quuu	100q quuu
04h	FSR (12C508)	Indirect da	ita mem	ory addr	ess poin	iter	1	1	1	111x xxxx	111u uuuu	111u uuuu
04h	FSR (12C509)	Indirect da	Indirect data memory address pointer								11uu uuuu	11uu uuuu
05h	OSCCAL	CAL7	CAL6	CAL5	CAL4	_		—		0111	uuuu	uuuu
06h	GPIO	—	—	GP5	GP4	GP3	GP2	GP1	GP0	xx xxxx	uu uuuu	uu uuuu

Legend: Shaded boxes = unimplemented or unused, - = unimplemented, read as '0' (if applicable) x = unknown, u = unchanged, q = see the tables in Section 7.7 for possible values.

Note 1: The upper byte of the Program Counter is not directly accessible. See Section 4.5 for an explanation of how to access these bits.



#### 4.3 STATUS Register

This register contains the arithmetic status of the ALU, the RESET status, and the page preselect bit for program memories larger than 512 words.

The STATUS register can be the destination for any instruction, as with any other register. If the STATUS register is the destination for an instruction that affects the Z, DC or C bits, then the write to these three bits is disabled. These bits are set or cleared according to the device logic. Furthermore, the TO and PD bits are not writable. Therefore, the result of an instruction with the STATUS register as destination may be different than intended.

For example, CLRF STATUS will clear the upper three bits and set the Z bit. This leaves the STATUS register as 000u uluu (where u = unchanged).

It is recommended, therefore, that only BCF, BSF and MOVWF instructions be used to alter the STATUS register because these instructions do not affect the Z, DC or C bits from the STATUS register. For other instructions, which do affect STATUS bits, see Instruction Set Summary.

#### FIGURE 4-4: STATUS REGISTER (ADDRESS:03h)

	R/W-0	R/W-0	<u>R-1</u>	<u>R-1</u>	R/W-x	R/W-x	R/W-x		
GPWUF	—	PA0	TO	PD	Z	DC	С	R = Readable bit	
it7	6	5	4	3	2	1	bit0	W = Writable bit - n = Value at POR reset	
	GPWUF: G								
	$1 = \text{Reset } \alpha$ $0 = \text{After } p \alpha$	due to wake ower up or o		LEEP on pi	n change				
it 6:	Unimplem	ented							
	Each page Using the F	(200h - 3F (000h - 1F is 512 byte A0 bit as a	Fh) - PIC12 Fh) - PIC12 s. general pu	2C509 2C508 and prose read				e it for program rith future products.	
	<b>TO</b> : Time-o 1 = After po 0 = A WDT	ower-up, CL		uction, or s	LEEP instruc	tion			
	<b>PD</b> : Power- 1 = After po 0 = By exec	ower-up or l			tion				
	<b>Z</b> : Zero bit 1 = The res 0 = The res			0 1	tion is zero tion is not ze	ro			
	<ul> <li>DC: Digit carry/borrow bit (for ADDWF and SUBWF instructions)</li> <li>ADDWF</li> <li>1 = A carry from the 4th low order bit of the result occurred</li> <li>0 = A carry from the 4th low order bit of the result did not occur</li> <li>SUBWF</li> </ul>								
					e result did no e result occur				
it 0:	C: Carry/bo	orrow bit (fo	r addwf, St	JBWF and R	RF, RLF instr	uctions)			



#### 4.4 OPTION Register

The OPTION register is a 8-bit wide, write-only register which contains various control bits to configure the Timer0/WDT prescaler and Timer0.

By executing the OPTION instruction, the contents of the W register will be transferred to the OPTION register. A RESET sets the OPTION<7:0> bits.

#### FIGURE 4-5: OPTION REGISTER

**Note:** If TRIS bit is set to '0', the wake-up on change and pull-up functions are disabled for that pin; i.e., note that TRIS overrides OPTION control of GPPU and GPWU.

Note: If the TOCS bit is set to '1', GP2 is forced to be an input even if TRIS GP2 = '0'.

W-1	W-1	W-1	W-1	W-1	W-1	W-1	W-1					
GPWU	GPPU	TOCS	TOSE	PSA	PS2	PS1	PS0	W = Writable bit				
bit7	6	5	4	3	2	1	bitO	U = Unimplemented bit - n = Value at POR reset Reference Table 4-1 for other resets.				
bit 7:	<b>GPWU:</b> Ena 1 = Disabled 0 = Enabled	d	ıp on pin c	hange (GP	0, GP1, GP3	)						
bit 6:	<b>GPPU</b> : Enable weak pull-ups (GP0, GP1, GP3) 1 = Disabled 0 = Enabled											
bit 5:	<b>TOCS</b> : Time 1 = Transitio 0 = Transitio	on on TOCK	l pin		ock, Fosc/4							
bit 4:	<b>TOSE</b> : Time 1 = Increme 0 = Increme	ent on high t	to low tran	sition on the								
bit 3:	<b>PSA</b> : Prescale 1 = Prescale 0 = Prescale	er assigned	to the WD									
bit 2-0:	<b>PS2:PS0</b> : P	rescaler rat	te select b	its								
	Bit Value	Timer0 R	ate WD1	Rate								
	000 001 010 011 100 101 110	1 : 2 1 : 4 1 : 8 1 : 16 1 : 32 1 : 64 1 : 128 1 : 256	1 : 3 1 :	2 4								



#### 4.5 Program Counter

As a program instruction is executed, the Program Counter (PC) will contain the address of the next program instruction to be executed. The PC value is increased by one every instruction cycle, unless an instruction changes the PC.

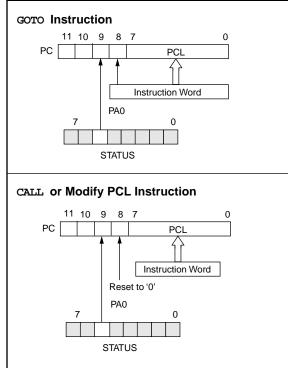
For a GOTO instruction, bits 8:0 of the PC are provided by the GOTO instruction word. The PC Latch (PCL) is mapped to PC<7:0>. Bit 5 of the STATUS register provides page information to bit 9 of the PC (Figure 4-6).

For a CALL instruction, or any instruction where the PCL is the destination, bits 7:0 of the PC again are provided by the instruction word. However, PC<8> does not come from the instruction word, but is always cleared (Figure 4-6).

Instructions where the PCL is the destination, or Modify PCL instructions, include MOVWF PC, ADDWF PC, and BSF PC, 5.

**Note:** Because PC<8> is cleared in the CALL instruction, or any Modify PCL instruction, all subroutine calls or computed jumps are limited to the first 256 locations of any program memory page (512 words long).

#### FIGURE 4-6: LOADING OF PC BRANCH INSTRUCTIONS -PIC12C508/C509



#### 4.5.1 EFFECTS OF RESET

The Program Counter is set upon a RESET, which means that the PC addresses the last location in the last page i.e., the oscillator calibration instruction. After executing MOVLW XX, the PC will roll over to location 00h, and begin executing user code.

The STATUS register page preselect bits are cleared upon a RESET, which means that page 0 is pre-selected.

Therefore, upon a RESET, a GOTO instruction will automatically cause the program to jump to page 0 until the value of the page bits is altered.

#### 4.6 Stack

PIC12C5XX devices have a 12-bit wide hardware push/pop stack.

A CALL instruction will *push* the current value of stack 1 into stack 2 and then push the current program counter value, incremented by one, into stack level 1. If more than two sequential CALL's are executed, only the most recent two return addresses are stored.

A RETLW instruction will *pop* the contents of stack level 1 into the program counter and then copy stack level 2 contents into level 1. If more than two sequential RETLW's are executed, the stack will be filled with the address previously stored in level 2. Note that the W register will be loaded with the literal value specified in the instruction. This is particularly useful for the implementation of data look-up tables within the program memory.



#### 4.7 Indirect Data Addressing; INDF and FSR Registers

The INDF register is not a physical register. Addressing INDF actually addresses the register whose address is contained in the FSR register (FSR is a *pointer*). This is indirect addressing.

#### EXAMPLE 4-1: INDIRECT ADDRESSING

- Register file 07 contains the value 10h
- Register file 08 contains the value 0Ah
- Load the value 07 into the FSR register
- A read of the INDF register will return the value of 10h
- Increment the value of the FSR register by one (FSR = 08)
- A read of the INDR register now will return the value of 0Ah.

Reading INDF itself indirectly (FSR = 0) will produce 00h. Writing to the INDF register indirectly results in a no-operation (although STATUS bits may be affected).

A simple program to clear RAM locations 10h-1Fh using indirect addressing is shown in Example 4-2.

#### EXAMPLE 4-2: HOW TO CLEAR RAM USING INDIRECT ADDRESSING

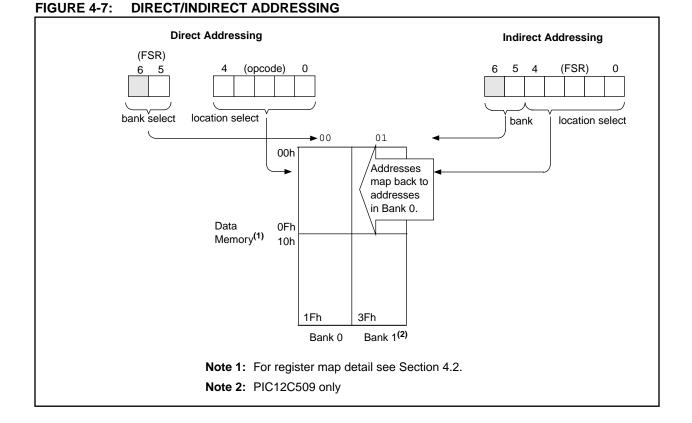
		-	
	movlw	0x10	;initialize pointer
	movwf	FSR	; to RAM
NEXT	clrf	INDF	clear INDF register;
	incf	FSR,F	;inc pointer
	btfsc	FSR,4	;all done?
	goto	NEXT	;NO, clear next
CONTINUE			
	:		;YES, continue

The FSR is a 5-bit wide register. It is used in conjunction with the INDF register to indirectly address the data memory area.

The FSR<4:0> bits are used to select data memory addresses 00h to 1Fh.

**PIC12C508:** Does not use banking. FSR<6:5> are unimplemented and read as '1's.

**PIC12C509:** Uses FSR<5>. Selects between bank 0 and bank 1. FSR<6> is unimplemented, read as '1'.



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# PIC12C5XX

NOTES:



#### 5.0 I/O PORT

As with any other register, the I/O register can be written and read under program control. However, read instructions (e.g., MOVF GPIO, W) always read the I/O pins independent of the pin's input/output modes. On RESET, all I/O ports are defined as input (inputs are at hi-impedance) since the I/O control registers are all set.

#### 5.1 <u>GPIO</u>

GPIO is an 8-bit I/O register. Only the low order 6 bits are used (GP5:GP0). Bits 7 and 6 are unimplemented and read as '0's. Please note that GP3 is an input only pin. The configuration word can set several I/O's to alternate functions. When acting as alternate functions the pins will read as '0' during port read. Pins GP0, GP1, and GP3 can be configured with weak pull-ups and also with wake-up on change. The wake-up on change and weak pull-up functions are not pin selectable. If pin 4 is configured as MCLR, weak pullup is always on and wake-up on change for this pin is not enabled.

#### 5.2 TRIS Register

The output driver control register is loaded with the contents of the W register by executing the TRIS f instruction. A '1' from a TRIS register bit puts the corresponding output driver in a hi-impedance mode. A '0' puts the contents of the output data latch on the selected pins, enabling the output buffer. The exceptions are GP3 which is input only and GP2 which may be controlled by the option register, see Section 4.4.

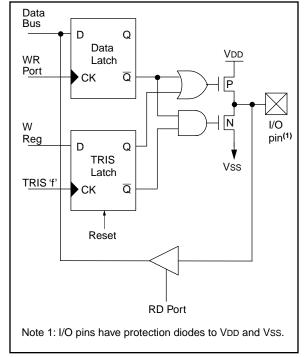
Note:	A read of the ports reads the pins, not the output data latches. That is, if an output
	driver on a pin is enabled and driven high,
	but the external system is holding it low, a
	read of the port will indicate that the pin is
	low.

The TRIS registers are "write-only" and are set (output drivers disabled) upon RESET.

#### 5.3 <u>I/O Interfacing</u>

The equivalent circuit for an I/O port pin is shown in Figure 5-1. All port pins, except GP3 which is input only, may be used for both input and output operations. For input operations these ports are non-latching. Any input must be present until read by an input instruction (e.g., MOVF GPIO, W). The outputs are latched and remain unchanged until the output latch is rewritten. To use a port pin as output, the corresponding direction control bit in TRIS must be cleared (= 0). For use as an input, the corresponding TRIS bit must be set. Any I/O pin (except GP3) can be programmed individually as input or output.

#### FIGURE 5-1: EQUIVALENT CIRCUIT FOR A SINGLE I/O PIN



#### TABLE 5-1: SUMMARY OF PORT REGISTERS

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-On Reset	Value on MCLR and WDT Reset	Value on Wake-up on Pin Change
N/A	TRIS	I/O contro	ol registe	ers						11 1111	11 1111	11 1111
N/A	OPTION	GPWU	GPPU	TOCS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111	1111 1111
03H	STATUS	GPWUF	—	PA0	TO	PD	Z	DC	С	0001 1xxx	000q quuu	100q quuu
06h	GPIO	—	—	GP5	GP4	GP3	GP2	GP1	GP0	xx xxxx	uu uuuu	uu uuuu

Legend: Shaded cells not used by Port Registers, read as '0', — = unimplemented, read as '0', x = unknown, u = unchanged, q = see tables in Section 7.7 for possible values.



#### 5.4 I/O Programming Considerations

#### 5.4.1 **BI-DIRECTIONAL I/O PORTS**

Some instructions operate internally as read followed by write operations. The BCF and BSF instructions, for example, read the entire port into the CPU, execute the bit operation and re-write the result. Caution must be used when these instructions are applied to a port where one or more pins are used as input/outputs. For example, a BSF operation on bit5 of GPIO will cause all eight bits of GPIO to be read into the CPU, bit5 to be set and the GPIO value to be written to the output latches. If another bit of GPIO is used as a bidirectional I/O pin (say bit0) and it is defined as an input at this time, the input signal present on the pin itself would be read into the CPU and rewritten to the data latch of this particular pin, overwriting the previous content. As long as the pin stays in the input mode, no problem occurs. However, if bit0 is switched into output mode later on, the content of the data latch may now be unknown.

Example 5-1 shows the effect of two sequential readmodify-write instructions (e.g., BCF, BSF, etc.) on an I/ O port.

A pin actively outputting a high or a low should not be driven from external devices at the same time in order to change the level on this pin ("wired-or", "wired-and"). The resulting high output currents may damage the chip.

#### EXAMPLE 5-1: **READ-MODIFY-WRITE** INSTRUCTIONS ON AN I/O PORT

; Initial GPIO Settings ; GPIO<5:3> Inputs ; GPIO<2:0> Outputs ; GPIO latch GPIO pins ; \_\_\_\_\_

;

	BCF	GPIO,	5	;01	-ppp	11	pppp
	BCF	GPIO,	4	;10	-ppp	11	pppp
	MOVLW	007h		;			
	TRIS	GPIO		;10	-ppp	11	pppp
;							

;Note that the user may have expected the pin ;values to be --00 pppp. The 2nd BCF caused ;GP5 to be latched as the pin value (High).

#### 5.4.2 SUCCESSIVE OPERATIONS ON I/O PORTS

The actual write to an I/O port happens at the end of an instruction cycle, whereas for reading, the data must be valid at the beginning of the instruction cycle (Figure 5-2). Therefore, care must be exercised if a write followed by a read operation is carried out on the same I/O port. The sequence of instructions should allow the pin voltage to stabilize (load dependent) before the next instruction, which causes that file to be read into the CPU, is executed. Otherwise, the previous state of that pin may be read into the CPU rather than the new state. When in doubt, it is better to separate these instructions with a NOP or another instruction not accessing this I/O port.

	, Q1  Q2  Q3  Q4	¦ Q1  Q2  Q3  Q4	Q1 Q2 Q3 Q4	Q1  Q2  Q3  Q4	1
Instruction	PC	Y PC + 1	<u>X PC+2</u>	( PC + 3	<ul> <li>This example shows a write to GPIO followed</li> <li>by a read from GPIO.</li> </ul>
fetched	MOVWF GPIO	MOVF GPIO,W	NOP	NOP	Data setup time = $(0.25 \text{ TCY} - \text{TPD})$
GP5:GP0	I I	1 1	¥		where: TCY = instruction cycle.
		1	<u></u>		TPD = propagation delay
		Port pin written here	Port pin sampled here		Therefore, at higher clock frequencies, a write followed by a read may be problematic.
nstruction	1				1
executed	1	MOVWF GPIO	MOVF GPIO,W	NOP	1
	1 1 1	(Write to GPIO)	(Read GPIO)		
	1	1	1 1		:
	1				1

#### FIGURE 5-2: SUCCESSIVE I/O OPERATION



#### 6.0 TIMER0 MODULE AND TMR0 REGISTER

The Timer0 module has the following features:

- 8-bit timer/counter register, TMR0
- Readable and writable
- 8-bit software programmable prescaler
- Internal or external clock select
  - Edge select for external clock

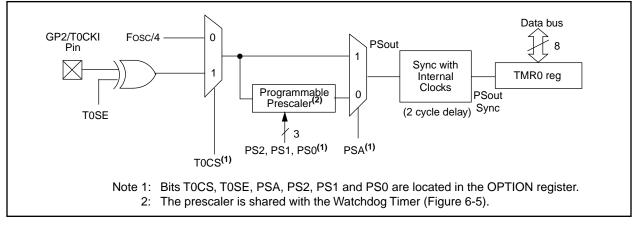
Figure 6-1 is a simplified block diagram of the Timer0 module.

Timer mode is selected by clearing the T0CS bit (OPTION<5>). In timer mode, the Timer0 module will increment every instruction cycle (without prescaler). If TMR0 register is written, the increment is inhibited for the following two cycles (Figure 6-2 and Figure 6-3). The user can work around this by writing an adjusted value to the TMR0 register.

Counter mode is selected by setting the T0CS bit (OPTION<5>). In this mode, Timer0 will increment either on every rising or falling edge of pin T0CKI. The T0SE bit (OPTION<4>) determines the source edge. Clearing the T0SE bit selects the rising edge. Restrictions on the external clock input are discussed in detail in Section 6.1.

The prescaler may be used by either the Timer0 module or the Watchdog Timer, but not both. The prescaler assignment is controlled in software by the control bit PSA (OPTION<3>). Clearing the PSA bit will assign the prescaler to Timer0. The prescaler is not readable or writable. When the prescaler is assigned to the Timer0 module, prescale values of 1:2, 1:4,..., 1:256 are selectable. Section 6.2 details the operation of the prescaler.

A summary of registers associated with the Timer0 module is found in Table 6-1.



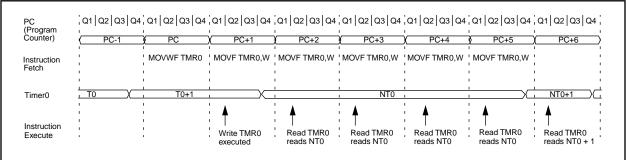
#### FIGURE 6-1: TIMER0 BLOCK DIAGRAM



#### FIGURE 6-2: TIMER0 TIMING: INTERNAL CLOCK/NO PRESCALE

(Program Counter)	PC-1	PC	PC+1	) PC+2	PC+3	) PC+4	§ PC+5 (	PC+6
Instruction Fetch		MOVWF TMR0	MOVF TMR0,W	MOVF TMR0,W	MOVF TMR0,W	MOVF TMR0,W	MOVF TMR0,W	
	1 1 1	1	1 1 1	1 1 1	1 1 1	1		_
Timer0	<u> </u>	<u>, T0+1 χ</u>	<u>, T0+2 χ</u>	<u>, NTO X</u>	<u>, ΝΤΟ χ</u>	<u>, ΝΤΟ Χ</u>	<u>, NT0+1 X ,</u>	NT0+2 χ
	1	1			. ▲	1	1 🔺 - 1	
Instruction	1		i T	i T	; T	T T	; <b>f</b> ;	Ť
Executed	1	1	Write TMR0	Read TMR0	Read TMR0	Read TMR0	Read TMR0	Read TMR0

#### FIGURE 6-3: TIMER0 TIMING: INTERNAL CLOCK/PRESCALE 1:2



#### TABLE 6-1: REGISTERS ASSOCIATED WITH TIMER0

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value Power Rese	-On	Valu MCLI WDT	Rand	Valu Wake- Pin Cl	up on
01h	TMR0	Timer0	- 8-bit re	al-time	clock/c	ounter				XXXX X	xxxx	uuuu	uuuu	uuuu	uuuu
N/A	OPTION	GPWU	PWU GPPU TOCS TOSE PSA PS2 PS1 PS0						PS0	1111 1	1111	1111	1111	1111	1111
N/A	TRIS	I/O cont	O control registers						11 1	1111	11	1111	11	1111	

Legend: Shaded cells not used by Timer0, - = unimplemented, x = unknown, u = unchanged,



#### 6.1 Using Timer0 with an External Clock

When an external clock input is used for Timer0, it must meet certain requirements. The external clock requirement is due to internal phase clock (Tosc) synchronization. Also, there is a delay in the actual incrementing of Timer0 after synchronization.

#### 6.1.1 EXTERNAL CLOCK SYNCHRONIZATION

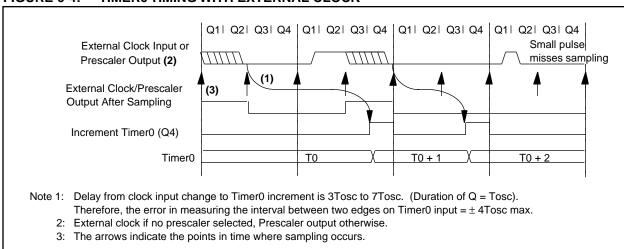
When no prescaler is used, the external clock input is the same as the prescaler output. The synchronization of T0CKI with the internal phase clocks is accomplished by sampling the prescaler output on the Q2 and Q4 cycles of the internal phase clocks (Figure 6-4). Therefore, it is necessary for T0CKI to be high for at least 2Tosc (and a small RC delay of 20 ns) and low for at least 2Tosc (and a small RC delay of 20 ns). Refer to the electrical specification of the desired device. When a prescaler is used, the external clock input is divided by the asynchronous ripple counter-type prescaler so that the prescaler output is symmetrical. For the external clock to meet the sampling requirement, the ripple counter must be taken into account. Therefore, it is necessary for TOCKI to have a period of at least 4TOSC (and a small RC delay of 40 ns) divided by the prescaler value. The only requirement on TOCKI high and low time is that they do not violate the minimum pulse width requirement of 10 ns. Refer to parameters 40, 41 and 42 in the electrical specification of the desired device.

#### 6.1.2 TIMER0 INCREMENT DELAY

Since the prescaler output is synchronized with the internal clocks, there is a small delay from the time the external clock edge occurs to the time the Timer0 module is actually incremented. Figure 6-4 shows the delay from the external clock edge to the timer incrementing.

#### 6.1.3 OPTION REGISTER EFFECT ON GP2 TRIS

If the option register is set to read TIMER0 from the pin, the port is forced to an input regardless of the TRIS register setting.



#### FIGURE 6-4: TIMER0 TIMING WITH EXTERNAL CLOCK



#### 6.2 <u>Prescaler</u>

An 8-bit counter is available as a prescaler for the Timer0 module, or as a postscaler for the Watchdog Timer (WDT), respectively (Section 7.6). For simplicity, this counter is being referred to as "prescaler" throughout this data sheet. Note that the prescaler may be used by either the Timer0 module or the WDT, but not both. Thus, a prescaler assignment for the Timer0 module means that there is no prescaler for the WDT, and vice-versa.

The PSA and PS2:PS0 bits (OPTION<3:0>) determine prescaler assignment and prescale ratio.

When assigned to the Timer0 module, all instructions writing to the TMR0 register (e.g., CLRF 1, MOVWF 1, BSF 1, x, etc.) will clear the prescaler. When assigned to WDT, a CLRWDT instruction will clear the prescaler along with the WDT. The prescaler is neither readable nor writable. On a RESET, the prescaler contains all '0's.

#### 6.2.1 SWITCHING PRESCALER ASSIGNMENT

The prescaler assignment is fully under software control (i.e., it can be changed "on the fly" during program execution). To avoid an unintended device RESET, the following instruction sequence (Example 6-1) must be executed when changing the prescaler assignment from Timer0 to the WDT.

### EXAMPLE 6-1: CHANGING PRESCALER (TIMER0 $\rightarrow$ WDT)

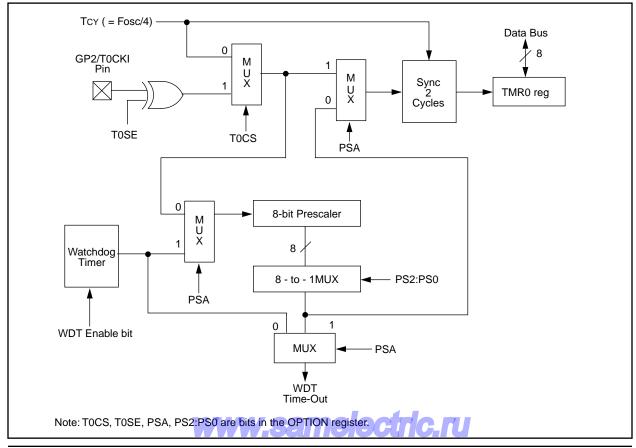
1.CLRWDT		;Clear WDT
2.CLRF 1	rmr0	;Clear TMR0 & Prescaler
3.MOVLW '	00xx1111'b;	;These 3 lines (5, 6, 7)
4.OPTION		; are required only if
		; desired
5.CLRWDT		;PS<2:0> are 000 or 001
6.MOVLW '	00xx1xxx′b	;Set Postscaler to
7.OPTION		; desired WDT rate

To change prescaler from the WDT to the Timer0 module, use the sequence shown in Example 6-2. This sequence must be used even if the WDT is disabled. A CLRWDT instruction should be executed before switching the prescaler.

EXAMPLE 6-2:	CHANGING PRESCALER
	(WDT→TIMER0)

CLRWDT		;Clear WDT and
		;prescaler
MOVLW	'xxxx0xxx'	;Select TMR0, new
		;prescale value and
		;clock source
OPTION		

#### FIGURE 6-5: BLOCK DIAGRAM OF THE TIMER0/WDT PRESCALER



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#### 7.0 SPECIAL FEATURES OF THE CPU

What sets a microcontroller apart from other processors are special circuits to deal with the needs of real-time applications. The PIC12C5XX family of microcontrollers has a host of such features intended to maximize system reliability, minimize cost through elimination of external components, provide power saving operating modes and offer code protection. These features are:

- Oscillator selection
- Reset
  - Power-On Reset (POR)
  - Device Reset Timer (DRT)
  - Wake-up from SLEEP on pin change
- Watchdog Timer (WDT)
- SLEEP
- Code protection
- ID locations
- In-circuit Serial Programming

The PIC12C5XX has a Watchdog Timer which can be shut off only through configuration bit WDTE. It runs off of its own RC oscillator for added reliability. If using XT or LP selectable oscillator options, there is always an 18 ms (nominal) delay provided by the Device Reset Timer (DRT), intended to keep the chip in reset until the crystal oscillator is stable. If using INTRC or EXTRC there is an 18 ms delay only on VDD power-up. With this timer on-chip, most applications need no external reset circuitry.

The SLEEP mode is designed to offer a very low current power-down mode. The user can wake-up from SLEEP through a change on input pins or through a Watchdog Timer time-out. Several oscillator options are also made available to allow the part to fit the application, including an internal 4 MHz oscillator. The EXTRC oscillator option saves system cost while the LP crystal option saves power. A set of configuration bits are used to select various options.

#### 7.1 Configuration Bits

The PIC12C5XX configuration word consists of 5 bits. Configuration bits can be programmed to select various device configurations. Two bits are for the selection of the oscillator type, one bit is the Watchdog Timer enable bit, and one bit is the  $\overline{\text{MCLR}}$  enable bit. One bit is the code protection bit (Figure 7-1).

#### FIGURE 7-1: CONFIGURATION WORD FOR PIC12C508 OR PIC12C509

							_		1				
			—	—	—	—	MCLRE	CP	WDTE	FOSC1	FOSC0	Register:	CONFIG
bit11	10	9	8	7	6	5	4	3	2	1	bit0	Address <sup>(1)</sup> :	FFFh
bit 11-5:	Unim	Unimplemented											
bit 4:	$1 = \overline{M}$	MCLRE: MCLR enable bit. 1 = MCLR pin enabled 0 = MCLR tied to VDD, (Internally)											
bit 3:	1 = Co	<b>CP:</b> Code protection bit. 1 = Code protection off 0 = Code protection on											
bit 2:	1 = W	WDTE: Watchdog timer enable bit 1 = WDT enabled 0 = WDT disabled											
bit 1-0:	11 = E 10 = I 01 = X	FOSC1:FOSC0: Oscillator selection bits 11 = EXTRC - external RC oscillator 10 = INTRC - internal RC oscillator 01 = XT oscillator 00 = LP oscillator											
Note 1:		00 = LP oscillator Refer to the PIC12C5XX Programming Specifications to determine how to access the configuration word. This register is not user addressable during device operation.									ıe		



#### 7.2 Oscillator Configurations

#### 7.2.1 OSCILLATOR TYPES

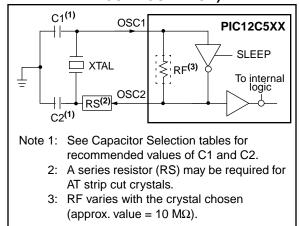
The PIC12C5XX can be operated in four different oscillator modes. The user can program two configuration bits (FOSC1:FOSC0) to select one of these four modes:

- LP: Low Power Crystal
- XT: Crystal/Resonator
- INTRC: Internal 4 MHz Oscillator
- EXTRC: External Resistor/Capacitor

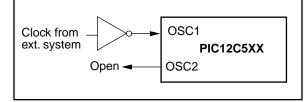
### 7.2.2 CRYSTAL OSCILLATOR / CERAMIC RESONATORS

In XT or LP modes, a crystal or ceramic resonator is connected to the GP5/OSC1/CLKIN and GP4/OSC2 pins to establish oscillation (Figure 7-2). The PIC12C5XX oscillator design requires the use of a parallel cut crystal. Use of a series cut crystal may give a frequency out of the crystal manufacturers specifications. When in XT or LP modes, the device can have an external clock source drive the GP5/ OSC1/CLKIN pin (Figure 7-3).

#### FIGURE 7-2: CRYSTAL OPERATION (OR CERAMIC RESONATOR) (XT OR LP OSC CONFIGURATION)



#### FIGURE 7-3: EXTERNAL CLOCK INPUT OPERATION (XT OR LP OSC CONFIGURATION)



# TABLE 7-1: CAPACITOR SELECTION FOR CERAMIC RESONATORS - PIC12C5XX

Osc	Resonator	Cap. Range	Cap. Range
Type	Freq	C1	C2
XT	4.0 MHz	30 pF	30 pF

These values are for design guidance only. Since each resonator has its own characteristics, the user should consult the resonator manufacturer for appropriate values of external components.

# TABLE 7-2:CAPACITOR SELECTION<br/>FOR CRYSTAL OSCILLATOR<br/>- PIC12C5XX

Osc Type	Resonator Freq	Cap.Range C1	Cap. Range C2
LP	32 kHz <sup>(1)</sup>	15 pF	15 pF
XT	200 kHz	47-68 pF	47-68 pF
	1 MHz	15 pF	15 pF
	4 MHz	15 pF	15 pF

Note 1: For VDD > 4.5V, C1 = C2  $\approx$  30 pF is recommended.

These values are for design guidance only. Rs may be required in XT mode to avoid overdriving crystals with low drive level specification. Since each crystal has its own characteristics, the user should consult the crystal manufacturer for appropriate values of external components.

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#### 7.2.3 EXTERNAL CRYSTAL OSCILLATOR CIRCUIT

Either a prepackaged oscillator or a simple oscillator circuit with TTL gates can be used as an external crystal oscillator circuit. Prepackaged oscillators provide a wide operating range and better stability. A well-designed crystal oscillator will provide good performance with TTL gates. Two types of crystal oscillator circuits can be used: one with parallel resonance, or one with series resonance.

Figure 7-4 shows implementation of a parallel resonant oscillator circuit. The circuit is designed to use the fundamental frequency of the crystal. The 74AS04 inverter performs the 180-degree phase shift that a parallel oscillator requires. The 4.7 k $\Omega$  resistor provides the negative feedback for stability. The 10 k $\Omega$  potentiometers bias the 74AS04 in the linear region. This circuit could be used for external oscillator designs.

#### FIGURE 7-4: EXTERNAL PARALLEL RESONANT CRYSTAL OSCILLATOR CIRCUIT

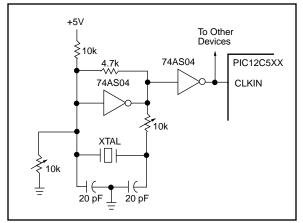
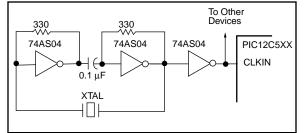


Figure 7-5 shows a series resonant oscillator circuit. This circuit is also designed to use the fundamental frequency of the crystal. The inverter performs a 180-degree phase shift in a series resonant oscillator circuit. The  $330 \Omega$  resistors provide the negative feedback to bias the inverters in their linear region.

#### FIGURE 7-5: EXTERNAL SERIES RESONANT CRYSTAL OSCILLATOR CIRCUIT



#### 7.2.4 EXTERNAL RC OSCILLATOR

For timing insensitive applications, the RC device option offers additional cost savings. The RC oscillator frequency is a function of the supply voltage, the resistor (Rext) and capacitor (Cext) values, and the operating temperature. In addition to this, the oscillator frequency will vary from unit to unit due to normal process parameter variation. Furthermore, the difference in lead frame capacitance between package types will also affect the oscillation frequency, especially for low Cext values. The user also needs to take into account variation due to tolerance of external R and C components used.

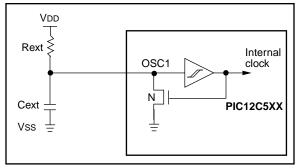
Figure 7-6 shows how the R/C combination is connected to the PIC12C5XX. For Rext values below 2.2 k $\Omega$ , the oscillator operation may become unstable, or stop completely. For very high Rext values (e.g., 1 M $\Omega$ ) the oscillator becomes sensitive to noise, humidity and leakage. Thus, we recommend keeping Rext between 3 k $\Omega$  and 100 k $\Omega$ .

Although the oscillator will operate with no external capacitor (Cext = 0 pF), we recommend using values above 20 pF for noise and stability reasons. With no or small external capacitance, the oscillation frequency can vary dramatically due to changes in external capacitances, such as PCB trace capacitance or package lead frame capacitance.

The Electrical Specifications sections show RC frequency variation from part to part due to normal process variation. The variation is larger for larger R (since leakage current variation will affect RC frequency more for large R) and for smaller C (since variation of input capacitance will affect RC frequency more).

Also, see the Electrical Specifications sections for variation of oscillator frequency due to VDD for given Rext/Cext values as well as frequency variation due to operating temperature for given R, C, and VDD values.

## FIGURE 7-6: EXTERNAL RC OSCILLATOR MODE



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#### 7.2.5 INTERNAL 4 MHz RC OSCILLATOR

The internal RC oscillator provides a fixed 4 MHz (nominal) system clock.

In addition, a calibration instruction is programmed into the top of memory which contains the calibration value for the internal RC oscillator. This value is programmed as a MOVLW XX instruction where XX is the calibration value, and is placed at the reset vector. This will load the W register with the calibration value upon reset and the PC will then roll over to the users program at address 0x000. The user then has the option of writing the value to the OSCCAL Register (05h) or ignoring it.

OSCCAL, when written to with the calibration value, will "trim" the internal oscillator to remove process variation from the oscillator frequency. The upper 4 bits of the register are used to allow for future, longer bit length calibration schemes. Writing a larger value in this location yields a higher clock speed.

Note: Please note that erasing the device will also erase the pre-programmed internal calibration value for the internal oscillator. The calibration value must be saved prior to erasing the part.

#### 7.3 <u>RESET</u>

The device differentiates between various kinds of reset:

- a) Power on reset (POR)
- b) MCLR reset during normal operation
- c) MCLR reset during SLEEP
- d) WDT time-out reset during normal operation
- e) WDT time-out reset during SLEEP
- f) Wake-up from SLEEP on pin change

Some registers are not reset in any way; they are unknown on POR and unchanged in any other reset. Most other registers are reset to "reset state" on poweron reset (POR), on  $\overline{\text{MCLR}}$ , WDT or wake-up on pin change reset during normal operation. They are not affected by a WDT reset during SLEEP or  $\overline{\text{MCLR}}$  reset during SLEEP, since these resets are viewed as resumption of normal operation. The exceptions to this are  $\overline{\text{TO}}$ ,  $\overline{\text{PD}}$ , and GPWUF bits. They are set or cleared differently in different reset situations. These bits are used in software to determine the nature of reset. See Table 7-3 for a full description of reset states of all registers.

Register	Address	Power-on Reset	MCLR Reset WDT time-out Wake-up on Pin Change
W	_	qqqq xxxx (1)	qqqq uuuu (1)
INDF	00h	XXXX XXXX	นนนน นนนน
TMR0	01h	XXXX XXXX	นนนน นนนน
PC	02h	1111 1111	1111 1111
STATUS	03h	0001 1xxx	?00? ?uuu (2)
FSR (12C508)	04h	111x xxxx	111u uuuu
FSR (12C509)	04h	110x xxxx	11uu uuuu
OSCCAL	05h	0111	uuuu
GPIO	06h	xx xxxx	uu uuuu
OPTION	—	1111 1111	1111 1111
TRIS	_	11 1111	11 1111

#### TABLE 7-3: RESET CONDITIONS FOR REGISTERS

Legend: u = unchanged, x = unknown, - = unimplemented bit, read as '0', ? = value depends on condition.

Note 1: Bits <7:4> of W register contain oscillator calibration values due to MOVLW XX instruction at top of memory.

Note 2: See Table 7-7 for reset value for specific conditions



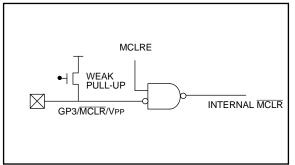
	STATUS Addr: 03h	PCL Addr: 02h		
Power on reset	0001 1xxx	1111 1111		
MCLR reset during normal operation	000u uuuu	1111 1111		
MCLR reset during SLEEP	0001 0uuuu	1111 1111		
WDT reset during SLEEP	0000 0uuu	1111 1111		
WDT reset normal operation	0000 luuu	1111 1111		
Wake-up from SLEEP on pin change	1001 Ouuu	1111 1111		

Legend: u = unchanged, x = unknown, - = unimplemented bit, read as '0'.

#### 7.3.1 MCLR ENABLE

This configuration bit when unprogrammed (left in the '1' state) enables the external  $\overline{\text{MCLR}}$  function. When programmed, the  $\overline{\text{MCLR}}$  function is tied to the internal VDD, and the pin is assigned to be a GPIO. See Figure 7-7.

FIGURE 7-7: MCLR SELECT



#### 7.4 Power-On Reset (POR)

The PIC12C5XX family incorporates on-chip Power-On Reset (POR) circuitry which provides an internal chip reset for most power-up situations.

A Power-on Reset pulse is generated on-chip when VDD rise is detected (in the range of 1.5V - 2.1V). To take advantage of the internal POR, program the GP3/ MCLR/VPP pin as MCLR and tie directly to VDD or program the pin as GP3. An internal weak pull-up resistor is implemented using a transistor. Refer to Table 10-6 for the pull-up resistor ranges. This will eliminate external RC components usually needed to create a Poweron Reset. A maximum rise time for VDD is specified. See Electrical Specifications for details.

When the device starts normal operation (exits the reset condition), device operating parameters (voltage, frequency, temperature, ...) must be met to ensure operation. If these conditions are not met, the device must be held in reset until the operating parameters are met.

A simplified block diagram of the on-chip Power-On Reset circuit is shown in Figure 7-8.

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The Power-On Reset circuit and the Device Reset Timer (Section 7.5) circuit are closely related. On power-up, the reset latch is set and the DRT is reset. The DRT timer begins counting once it detects  $\overline{\text{MCLR}}$ to be high. After the time-out period, which is typically 18 ms, it will reset the reset latch and thus end the onchip reset signal.

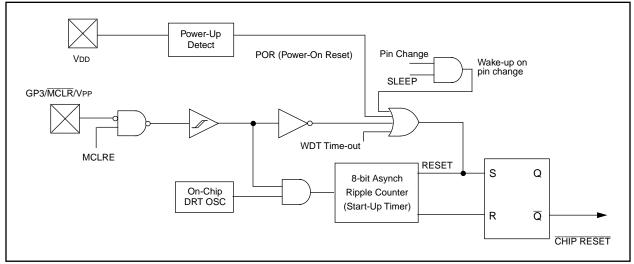
A power-up example where  $\overline{\text{MCLR}}$  is held low is shown in Figure 7-9. VDD is allowed to rise and stabilize before bringing  $\overline{\text{MCLR}}$  high. The chip will actually come out of reset TDRT msec after  $\overline{\text{MCLR}}$  goes high.

In Figure 7-10, the on-chip Power-On Reset feature is being used (MCLR and VDD are tied together or the pin is programmed to be GP3.). The VDD is stable before the start-up timer times out and there is no problem in getting a proper reset. However, Figure 7-11 depicts a problem situation where VDD rises too slowly. The time between when the DRT senses that MCLR is high and when MCLR (and VDD) actually reach their full value, is too long. In this situation, when the start-up timer times out, VDD has not reached the VDD (min) value and the chip is, therefore, not guaranteed to function correctly. For such situations, we recommend that external RC circuits be used to achieve longer POR delay times (Figure 7-10).

Note: When the device starts normal operation (exits the reset condition), device operating parameters (voltage, frequency, temperature, etc.) must be meet to ensure operation. If these conditions are not met, the device must be held in reset until the operating conditions are met.

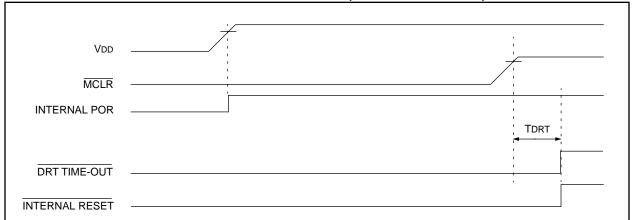
For additional information refer to Application Notes "Power-Up Considerations" - AN522 and "Power-up Trouble Shooting" - AN607.

#### FIGURE 7-8: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT

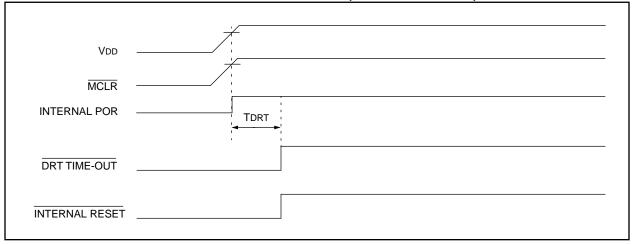




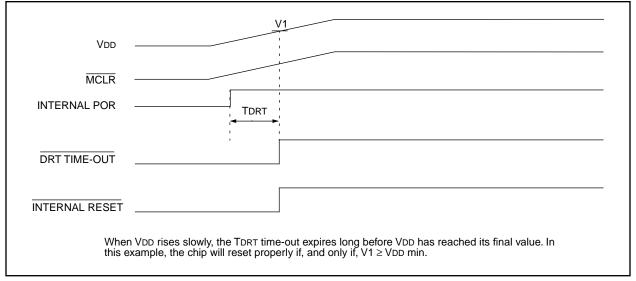
#### FIGURE 7-9: TIME-OUT SEQUENCE ON POWER-UP (MCLR PULLED LOW)



#### FIGURE 7-10: TIME-OUT SEQUENCE ON POWER-UP (MCLR TIED TO VDD): FAST VDD RISE TIME



#### FIGURE 7-11: TIME-OUT SEQUENCE ON POWER-UP (MCLR TIED TO VDD): SLOW VDD RISE TIME





#### 7.5 Device Reset Timer (DRT)

In the PIC12C5XX, the DRT runs any time the device is powered up. DRT runs from RESET and varies based on oscillator selection (see Table 7-5.)

The Device Reset Timer (DRT) provides a fixed 18 ms nominal time-out on reset. The DRT operates on an internal RC oscillator. The processor is kept in RESET as long as the DRT is active. The DRT delay allows VDD to rise above VDD min., and for the oscillator to stabilize.

Oscillator circuits based on crystals or ceramic resonators require a certain time after power-up to establish a stable oscillation. The on-chip DRT keeps the device in a RESET condition for approximately 18 ms after MCLR has reached a logic high (VIHMCLR) level. Thus, programming GP3/MCLR/VPP as MCLR and using an external RC network connected to the MCLR input is not required in most cases, allowing for savings in cost-sensitive and/or space restricted applications, as well as allowing the use of the GP3/MCLR/VPP pin as a general purpose input.

The Device Reset time delay will vary from chip to chip due to VDD, temperature, and process variation. See AC parameters for details.

The DRT will also be triggered upon a Watchdog Timer time-out (only in XT and LP modes). This is particularly important for applications using the WDT to wake from SLEEP mode automatically.

#### 7.6 <u>Watchdog Timer (WDT)</u>

The Watchdog Timer (WDT) is a free running on-chip RC oscillator which does not require any external components. This RC oscillator is separate from the external RC oscillator of the GP5/OSC1/CLKIN pin and the internal 4 MHz oscillator. That means that the WDT will run even if the main processor clock has been stopped, for example, by execution of a SLEEP instruction. During normal operation or SLEEP, a WDT reset or wake-up reset generates a device RESET.

The  $\overline{\text{TO}}$  bit (STATUS<4>) will be cleared upon a Watchdog Timer reset.

The WDT can be permanently disabled by programming the configuration bit WDTE as a '0' (Section 7.1). Refer to the PIC12C5XX Programming Specifications to determine how to access the configuration word.

#### TABLE 7-5:DRT (DEVICE RESET TIMER PERIOD)

Oscillator Configuration	POR Reset	Subsequent Resets
IntRC & ExtRC	18 ms (typical)	300 μs (typical)
XT & LP	18 ms (typical)	18 ms (typical)



#### 7.6.1 WDT PERIOD

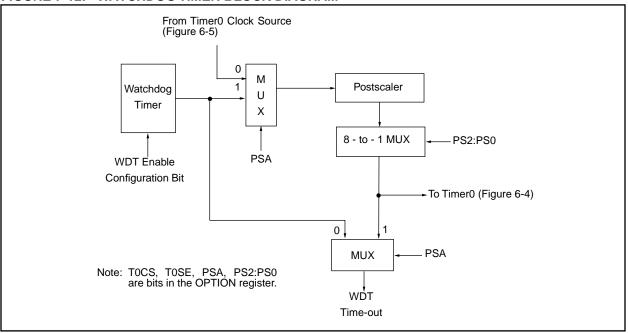
The WDT has a nominal time-out period of 18 ms, (with no prescaler). If a longer time-out period is desired, a prescaler with a division ratio of up to 1:128 can be assigned to the WDT (under software control) by writing to the OPTION register. Thus, a time-out period of a nominal 2.3 seconds can be realized. These periods vary with temperature, VDD and part-to-part process variations (see DC specs).

Under worst case conditions (VDD = Min., Temperature = Max., max. WDT prescaler), it may take several seconds before a WDT time-out occurs.

#### 7.6.2 WDT PROGRAMMING CONSIDERATIONS

The CLRWDT instruction clears the WDT and the postscaler, if assigned to the WDT, and prevents it from timing out and generating a device RESET.

The SLEEP instruction resets the WDT and the postscaler, if assigned to the WDT. This gives the maximum SLEEP time before a WDT wake-up reset.



#### FIGURE 7-12: WATCHDOG TIMER BLOCK DIAGRAM

TABLE 7-6:SUMMARY OF REGISTERS ASSOCIATED WITH THE WATCHDOG TIMER

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-On Reset	Value on MCLR and WDT Reset	Value on Wake-up on Pin Change
N/A	OPTION	GPWU	GPPU	TOCS	TOSE	PSA	PS2	PS1	PS0	1111 1111	1111 1111	1111 1111

Legend: Shaded boxes = Not used by Watchdog Timer, - = unimplemented, read as '0', u = unchanged



#### 7.7 <u>Time-Out Sequence, Power Down,</u> and Wake-up from SLEEP Status Bits (TO/PD/GPWUF)

The  $\overline{\text{TO}}$ ,  $\overline{\text{PD}}$ , and GPWUF bits in the STATUS register can be tested to determine if a RESET condition has been caused by a power-up condition, a  $\overline{\text{MCLR}}$  or Watchdog Timer (WDT) reset, or a  $\overline{\text{MCLR}}$  or WDT reset.

<b>TABLE 7-7:</b>	TO/PD/GPWUF STATUS		
	AFTER RESET		

GPWUF	TO	PD	RESET caused by
0	0	0	WDT wake-up from SLEEP
0	0	1	WDT time-out (not from SLEEP)
0	1	0	MCLR wake-up from SLEEP
0	1	1	Power-up
0	u	u	MCLR not during SLEEP
1	1	0	Wake-up from SLEEP on pin change

Legend: Legend: u = unchanged

Note 1: The TO, PD, and GPWUF bits maintain their status (u) until a reset occurs. A low-pulse on the MCLR input does not change the TO, PD, and GPWUF status bits.

These STATUS bits are only affected by events listed in Table 7-8.

## TABLE 7-8:EVENTS AFFECTING TO/PDSTATUS BITS

Event	GPWUF	TO	PD	Remarks
Power-up	0	1	1	
WDT Time-out	0	0	u	No effect on PD
SLEEP instruction	u	1	0	
CLRWDT instruction	u	1	1	
Wake-up from SLEEP on pin change	1	1	0	

Legend: u = unchanged

A WDT time-out will occur regardless of the status of the  $\overline{\text{TO}}$  bit. A SLEEP instruction will be executed, regardless of the status of the  $\overline{\text{PD}}$  bit. Table 7-7 reflects the status of  $\overline{\text{TO}}$  and  $\overline{\text{PD}}$  after the corresponding event.

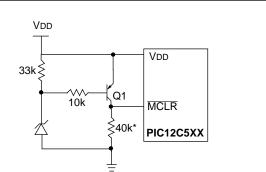
Table 7-4 lists the reset conditions for the special function registers, while Table 7-3 lists the reset conditions for all the registers.

#### 7.8 Reset on Brown-Out

A brown-out is a condition where device power (VDD) dips below its minimum value, but not to zero, and then recovers. The device should be reset in the event of a brown-out.

To reset PIC12C5XX devices when a brown-out occurs, external brown-out protection circuits may be built, as shown in Figure 7-13 and Figure 7-14.

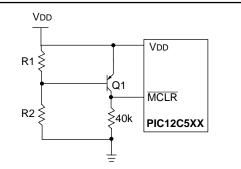
FIGURE 7-13:	<b>BROWN-OUT PROTECTION</b>
	CIRCUIT 1



This circuit will activate reset when VDD goes below Vz + 0.7V (where Vz = Zener voltage).

\*Refer to Figure 7-7 and Table 10-6 for internal weak pullup on MCLR.

#### FIGURE 7-14: BROWN-OUT PROTECTION CIRCUIT 2



This brown-out circuit is less expensive, although less accurate. Transistor Q1 turns off when VDD is below a certain level such that:

$$VDD \bullet \frac{R1}{R1 + R2} = 0.7V$$

\*Refer to Figure 7-7 and Table 10-6 for internal weak pull-up on  $\overline{\text{MCLR}}.$ 



#### 7.9 Power-Down Mode (SLEEP)

A device may be powered down (SLEEP) and later powered up (Wake-up from SLEEP).

#### 7.9.1 SLEEP

The Power-Down mode is entered by executing a SLEEP instruction.

If enabled, the Watchdog Timer will be cleared but keeps running, the  $\overline{TO}$  bit (STATUS<4>) is set, the  $\overline{PD}$  bit (STATUS<3>) is cleared and the oscillator driver is turned off. The I/O ports maintain the status they had before the SLEEP instruction was executed (driving high, driving low, or hi-impedance).

It should be noted that a RESET generated by a WDT time-out does not drive the  $\overline{\text{MCLR}}$  pin low.

For lowest current consumption while powered down, the T0CKI input should be at VDD or VSs and the GP3/ MCLR/VPP pin must be at a logic high level (VIHMC) if MCLR is enabled.

#### 7.9.2 WAKE-UP FROM SLEEP

The device can wake-up from SLEEP through one of the following events:

- 1. An external reset input on GP3/MCLR/VPP pin, when configured as MCLR.
- 2. A Watchdog Timer time-out reset (if WDT was enabled).
- A change on input pin GP0, GP1, or GP3/ MCLR/VPP when wake-up on change is enabled.

These events cause a device reset. The  $\overline{\text{TO}}$ ,  $\overline{\text{PD}}$ , and GPWUF bits can be used to determine the cause of device reset. The  $\overline{\text{TO}}$  bit is cleared if a WDT time-out occurred (and caused wake-up). The  $\overline{\text{PD}}$  bit, which is set on power-up, is cleared when SLEEP is invoked. The GPWUF bit indicates a change in state while in SLEEP at pins GP0, GP1, or GP3 (since the last time there was a file or bit operation on GP port).

**Caution:** Right before entering SLEEP, read the input pins. When in SLEEP, wake up occurs when the values at the pins change from the state they were in at the last reading. If a wake-up on change occurs and the pins are not read before reentering SLEEP, a wake up will occur immediately even if no pins change while in SLEEP mode.

The WDT is cleared when the device wakes from sleep, regardless of the wake-up source.

#### 7.10 Program Verification/Code Protection

If the code protection bit has not been programmed, the on-chip program memory can be read out for verification purposes.

The first 64 locations can be read regardless of the code protection bit setting.

#### 7.11 ID Locations

Four memory locations are designated as ID locations where the user can store checksum or other codeidentification numbers. These locations are not accessible during normal execution but are readable and writable during program/verify.

Use only the lower 4 bits of the ID locations and always program the upper 8 bits as '0's.



#### 7.12 In-Circuit Serial Programming

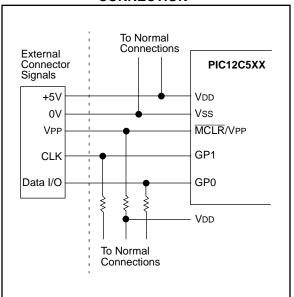
The PIC12C5XX microcontrollers can be serially programmed while in the end application circuit. This is simply done with two lines for clock and data, and three other lines for power, ground, and the programming voltage. This allows customers to manufacture boards with unprogrammed devices, and then program the microcontroller just before shipping the product. This also allows the most recent firmware or a custom firmware to be programmed.

The device is placed into a program/verify mode by holding the GP1 and GP0 pins low while raising the  $\overline{\text{MCLR}}$  (VPP) pin from VIL to VIHH (see programming specification). GP1 becomes the programming clock and GP0 becomes the programming data. Both GP1 and GP0 are Schmitt Trigger inputs in this mode.

After reset, a 6-bit command is then supplied to the device. Depending on the command, 14-bits of program data are then supplied to or from the device, depending if the command was a load or a read. For complete details of serial programming, please refer to the PIC12C5XX Programming Specifications.

A typical in-circuit serial programming connection is shown in Figure 7-15.

#### FIGURE 7-15: TYPICAL IN-CIRCUIT SERIAL PROGRAMMING CONNECTION





## 8.0 INSTRUCTION SET SUMMARY

Each PIC12C5XX instruction is a 12-bit word divided into an OPCODE, which specifies the instruction type, and one or more operands which further specify the operation of the instruction. The PIC12C5XX instruction set summary in Table 8-2 groups the instructions into byte-oriented, bit-oriented, and literal and control operations. Table 8-1 shows the opcode field descriptions.

For **byte-oriented** instructions, 'f' represents a file register designator and 'd' represents a destination designator. The file register designator is used to specify which one of the 32 file registers is to be used by the instruction.

The destination designator specifies where the result of the operation is to be placed. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed in the file register specified in the instruction.

For **bit-oriented** instructions, 'b' represents a bit field designator which selects the number of the bit affected by the operation, while 'f' represents the number of the file in which the bit is located.

For **literal and control** operations, 'k' represents an 8 or 9-bit constant or literal value.

#### TABLE 8-1: OPCODE FIELD DESCRIPTIONS

Field	Description	b = 3-bit bit ac f = 5-bit file re
f	Register file address (0x00 to 0x7F)	Literal and control
W	Working register (accumulator)	
b	Bit address within an 8-bit file register	OPCODE
k	Literal field, constant data or label	k = 8-bit imm
x	Don't care location (= 0 or 1) The assembler will generate code with $x = 0$ . It is the recommended form of use for compatibility with all Microchip software tools.	Literal and control
d	Destination select; d = 0 (store result in W) d = 1 (store result in file register 'f') Default is d = 1	k = 9-bit imm
label	Label name	
TOS	Top of Stack	
PC	Program Counter	
WDT	Watchdog Timer Counter	
TO	Time-Out bit	
PD	Power-Down bit	
dest	Destination, either the W register or the specified register file location	
[]	Options	
()	Contents	
$\rightarrow$	Assigned to	
< >	Register bit field	
€	In the set of	
italics	User defined term (font is courier)	
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All instructions are executed within a single instruction cycle, unless a conditional test is true or the program counter is changed as a result of an instruction. In this case, the execution takes two instruction cycles. One instruction cycle consists of four oscillator periods. Thus, for an oscillator frequency of 4 MHz, the normal instruction execution time is 1  $\mu$ s. If a conditional test is true or the program counter is changed as a result of an instruction, the instruction execution time is 2  $\mu$ s.

Figure 8-1 shows the three general formats that the instructions can have. All examples in the figure use the following format to represent a hexadecimal number:

0xhhh

where 'h' signifies a hexadecimal digit.

# FIGURE 8-1: GENERAL FORMAT FOR INSTRUCTIONS

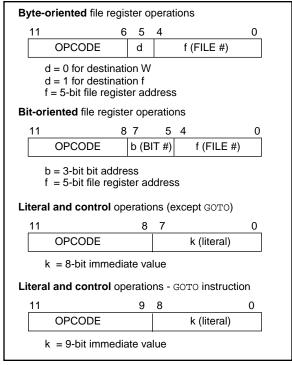


TABLE 8-2: INSTRUCTION SET SUMM	ARY
---------------------------------	-----

Mnemonic,				12-	12-Bit Opcode			
Operan		Description	Cycles	MSb		LSb	Status Affected	Notes
ADDWF	f,d	Add W and f	1	0001	11df	ffff	C,DC,Z	1,2,4
ANDWF	f,d	AND W with f	1	0001	01df	ffff	Z	2,4
CLRF	f	Clear f	1	0000	011f	ffff	Z	4
CLRW	-	Clear W	1	0000	0100	0000	Z	
COMF	f, d	Complement f	1	0010	01df	ffff	Z	
DECF	f, d	Decrement f	1	0000	11df	ffff	Z	2,4
DECFSZ	f, d	Decrement f, Skip if 0	1(2)	0010	11df	ffff	None	2,4
INCF	f, d	Increment f	1	0010	10df	ffff	Z	2,4
INCFSZ	f, d	Increment f, Skip if 0	1(2)	0011	11df	ffff	None	2,4
IORWF	f, d	Inclusive OR W with f	1	0001	00df	ffff	Z	2,4
MOVF	f, d	Move f	1	0010	00df	ffff	Z	2,4
MOVWF	f	Move W to f	1	0000	001f	ffff	None	1,4
NOP	-	No Operation	1	0000	0000	0000	None	
RLF	f, d	Rotate left f through Carry	1	0011	01df	ffff	С	2,4
RRF	f, d	Rotate right f through Carry	1	0011	00df	ffff	С	2,4
SUBWF	f, d	Subtract W from f	1	0000	10df	ffff	C,DC,Z	1,2,4
SWAPF	f, d	Swap f	1	0011	10df	ffff	None	2,4
XORWF	f, d	Exclusive OR W with f	1	0001	10df	ffff	Z	2,4
BIT-ORIENT	FED FIL	E REGISTER OPERATIONS						
BCF	f, b	Bit Clear f	1	0100	bbbf	ffff	None	2,4
BSF	f, b	Bit Set f	1	0101	bbbf	ffff	None	2,4
BTFSC	f, b	Bit Test f, Skip if Clear	1 (2)	0110	bbbf	ffff	None	
BTFSS	f, b	Bit Test f, Skip if Set	1 (2)	0111	bbbf	ffff	None	
LITERAL A	ND CO	NTROL OPERATIONS						
ANDLW	k	AND literal with W	1	1110	kkkk	kkkk	Z	
CALL	k	Call subroutine	2	1001	kkkk	kkkk	None	1
CLRWDT	k	Clear Watchdog Timer	1	0000	0000	0100	TO, PD	
GOTO	k	Unconditional branch	2	101k	kkkk	kkkk	None	
IORLW	k	Inclusive OR Literal with W	1	1101	kkkk	kkkk	Z	
MOVLW	k	Move Literal to W	1	1100	kkkk	kkkk	None	
OPTION	-	Load OPTION register	1	0000	0000	0010	None	
RETLW	k	Return, place Literal in W	2	1000	kkkk	kkkk	None	
SLEEP	-	Go into standby mode	1	0000	0000	0011	TO, PD	
TRIS	f	Load TRIS register	1	0000	0000	Offf	None	3
XORLW	k	Exclusive OR Literal to W	1	1111	kkkk	kkkk	Z	

Note 1: The 9th bit of the program counter will be forced to a '0' by any instruction that writes to the PC except forGOTO. (Section 4.5)

2: When an I/O register is modified as a function of itself (e.g. MOVF GPIO, 1), the value used will be that value present on the pins themselves. For example, if the data latch is '1' for a pin configured as input and is driven low by an external device, the data will be written back with a '0'.

3: The instruction TRIS f, where f = 6 causes the contents of the W register to be written to the tristate latches of GPIO. A '1' forces the pin to a hi-impedance state and disables the output buffers.

4: If this instruction is executed on the TMR0 register (and, where applicable, d = 1), the prescaler will be cleared (if assigned to TMR0).



ADDWF	Add W and f				
Syntax:	[label]A	DDWF	f,d		
Operands:	$0 \le f \le 31$				
	$d \in [0,1]$				
Operation:	(W) + (f)	$\rightarrow$ (dest)			
Status Affected:	C, DC, Z				
Encoding:	0001	11df	ffff		
Description:	Add the contents of the W register and register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is '1' the result is stored back in register 'f'.				
Words:	1				
Cycles:	1				
Example:	ADDWF	FSR, O			
Before Instru	ction				
W =	0x17				
FSR =	0xC2				
After Instruct					
W = FSR =	0xD9 0xC2				
F3K =	0.02				

ANDWF		with f			
Syntax:	[label] A	NDWF	f,d		
Operands:	$0 \le f \le 31$ $d \in [0,1]$				
Operation:	(W) .AND	). (f) $\rightarrow$ (d	est)		
Status Affected:	Z				
Encoding:	0001	01df	ffff		
Description:	The contents of the W register are AND'ed with register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is '1' the result is stored back in register 'f'.				
Words:	1				
Cycles:	1				
Example:	ANDWF H	FSR,	1		
Before Instru W = FSR =	0x17				
After Instructi W = FSR =	ion 0x17 0x02				

ANDLW	And lite	ral with V	V	
Syntax:	[ <i>label</i> ] ANDLW k			
Operands:	$0 \le k \le 255$			
Operation:	(W).AND	. (k) $\rightarrow$ (V	V)	
Status Affected:	Z			
Encoding:	1110	kkkk	kkkk	
Description:	AND'ed w	ith the eig	W register ht-bit litera e W registe	l 'k'. The
Words:	1			
Cycles:	1			
Example:	ANDLW	0x5F		
Before Instru	iction			
W =	0xA3			
After Instruct	tion			
W =	0x03			

BCF	Bit Clear	r f		
Syntax:	[label] BCF f,b			
Operands:	$\begin{array}{l} 0 \leq f \leq 31 \\ 0 \leq b \leq 7 \end{array}$			
Operation:	$0 \rightarrow (f < b >)$			
Status Affected: None				
Encoding:	0100	bbbf	ffff	
Description:	Bit 'b' in register 'f' is cleared.			
Words:	1			
Cycles:	1			
Example:	BCF	FLAG_REG	G, 7	
Before Instruction FLAG_REG = 0xC7				
After Instruction FLAG_REG = 0x47				



BSF	Bit Set f				
Syntax:	[label] BSF f,b				
Operands:	$\begin{array}{l} 0 \leq f \leq 31 \\ 0 \leq b \leq 7 \end{array}$				
Operation:	$1 \rightarrow (f < b >)$				
Status Affected:	None				
Encoding:	0101	bbbf	ffff		
Description:	Bit 'b' in register 'f' is set.				
Words:	1				
Cycles:	1				
Example:	BSF	FLAG_REG	G, 7		
Before Instruction FLAG_REG = 0x0A					
After Instruction FLAG_REG = 0x8A					
BTFSC	Bit Test	f, Skip if	Clear		

BTFSC	Bit	Bit Test f, Skip if Clear			
Syntax:	[ lab	oel]	BTFSC	f,b	
Operands:		f ≤ 3′ b ≤ 7	-		
Operation:	skip	if (f<	<b>) = 0</b>		
Status Affect	ted: Nor	ne			
Encoding:	01	10	bbbf	ffff	
Description:	instr If bit fetch exec exec	uctior 'b' is ned du cution	n is skippe 0 then the uring the c is discard instead, m	' is 0 then the next d. next instruction urrent instruction ed, and an NOP is aking this a 2 cycle	
Words:	1				
Cycles:	1(2)				
Example:	HER FAL TRU	SE	BTFSC GOTO •	FLAG,1 PROCESS_CODE	
Before I PC	nstruction	=	address	(HERE)	
PC	struction _AG<1> _AG<1>	= = =	0, address ( 1, address(1		

BTFSS	Bit Test	f, Skip if	Set				
Syntax:	[ label ]	BTFSS	f,b				
Operands:	0 ≤ f ≤ 3 0 ≤ b < 7	-					
Operation:	skip if (f	skip if (f <b>) = 1</b>					
Status Affected:	None	None					
Encoding:	0111	bbbf	ffff				
Description:	If bit 'b' in register 'f' is '1' then the next instruction is skipped. If bit 'b' is '1', then the next instruction fetched during the current instruction execution, is discarded and an NOP is executed instead, making this a 2 cycle instruction.						
Words:	1						
Cycles:	1(2)						
Example:	HERE FALSE TRUE •		FLAG,1 PROCESS_C	CODE			
Before Instruction PC = address (HERE)							
After Instruc If FLAG< PC if FLAG< PC	:1> = =	0, address 1, address	(FALSE); (TRUE)				



CALL	Subrouti	ne Call			
Syntax:	[ <i>label</i> ] CALL k				
Operands:	$0 \le k \le 255$				
Operation:	$\begin{array}{l} (PC) + 1 \rightarrow Top \ of \ Stack; \\ k \rightarrow PC{<}7:0{>}; \\ (STATUS{<}6:5{>}) \rightarrow PC{<}10:9{>}; \\ 0 \rightarrow PC{<}8{>} \end{array}$				
Status Affected:	None				
Encoding:	1001	kkkk	kkkk		
Description:	Subroutine call. First, return address (PC+1) is pushed onto the stack. The eight bit immediate address is loaded into PC bits <7:0>. The upper bits PC<10:9> are loaded from STA- TUS<6:5>, PC<8> is cleared. CALL is a two cycle instruction.				
Words:	1				
Cycles:	2				
Example:	HERE (	CALL	THERE		
Before Instruction PC = address (HERE)					
After Instruction PC = address (THERE) TOS = address (HERE + 1)					

#### CLRF

	oleal I				
Syntax:	[label] CLRF f				
Operands:	$0 \le f \le 31$				
Operation:	$\begin{array}{c} 00h \rightarrow (f) \\ 1 \rightarrow Z \end{array}$	$\begin{array}{l} 00h \rightarrow (f); \\ 1 \rightarrow Z \end{array}$			
Status Affected:	Z				
Encoding:	0000	011f	ffff		
Description:	The contents of register 'f' are cleared and the Z bit is set.				
Words:	1				
Cycles:	1				
Example:	CLRF	FLAG_REC	7		
Before Instru FLAG_RE		0x5A			
After Instruct FLAG_RI Z		0x00 1			

Clear f

CLRW	Clear W
Syntax:	[label] CLRW
Operands:	None
Operation:	$\begin{array}{l} \text{00h} \rightarrow (\text{W}); \\ 1 \rightarrow \text{Z} \end{array}$
Status Affected:	Z
Encoding:	0000 0100 0000
Description:	The W register is cleared. Zero bit (Z) is set.
Words:	1
Cycles:	1
Example:	CLRW
Before Instru W =	
After Instruct W = Z =	tion 0x00 1
CLRWDT	Clear Watchdog Timer
Syntax:	[label] CLRWDT
Operands:	None
Operation:	$\begin{array}{l} 00h \rightarrow WDT; \\ 0 \rightarrow WDT \mbox{ prescaler (if assigned);} \\ 1 \rightarrow \overline{TO;} \\ 1 \rightarrow \overline{PD} \end{array}$
Operation: Status Affected:	$0 \rightarrow WDT$ prescaler (if assigned); 1 $\rightarrow \overline{TO}$ ;
	$0 \rightarrow WDT$ prescaler (if assigned); $1 \rightarrow \overline{TO};$ $1 \rightarrow \overline{PD}$
Status Affected:	$\begin{array}{l} 0 \rightarrow \text{WDT prescaler (if assigned);} \\ 1 \rightarrow \overline{\text{TO}}; \\ 1 \rightarrow \overline{\text{PD}} \\ \overline{\text{TO}}, \overline{\text{PD}} \end{array}$
Status Affected: Encoding:	$\begin{array}{l} 0 \rightarrow \text{WDT prescaler (if assigned);} \\ 1 \rightarrow \overline{\text{TO};} \\ 1 \rightarrow \overline{\text{PD}} \\ \hline \overline{\text{TO}, \ \overline{\text{PD}}} \\ \hline \hline \hline 0000  0000  0100 \\ \hline \hline \\ \text{The } \text{CLRWDT instruction resets the} \\ \text{WDT. It also resets the prescaler, if the} \\ \text{prescaler is assigned to the WDT and} \\ \text{not Timer0. Status bits TO and } \overline{\text{PD}} \text{ are} \end{array}$
Status Affected: Encoding: Description:	$\begin{array}{l} 0 \rightarrow \text{WDT prescaler (if assigned);} \\ 1 \rightarrow \overline{\text{TO};} \\ 1 \rightarrow \overline{\text{PD}} \\ \hline \overline{\text{TO}, \ \overline{\text{PD}}} \\ \hline \hline \end{array}$ $\begin{array}{c} \hline 0000 & 0000 & 0100 \\ \hline \end{array}$ The CLRWDT instruction resets the WDT. It also resets the prescaler, if the prescaler is assigned to the WDT and not Timer0. Status bits TO and PD are set.
Status Affected: Encoding: Description: Words:	$\begin{array}{l} 0 \rightarrow \text{WDT prescaler (if assigned);} \\ 1 \rightarrow \overline{\text{TO};} \\ 1 \rightarrow \overline{\text{PD}} \\ \hline \overline{\text{TO}, \ \overline{\text{PD}}} \\ \hline \hline \hline 0000 & 0000 & 0100 \\ \hline \hline \\ \hline \text{The } \text{CLRWDT instruction resets the} \\ \text{WDT. It also resets the prescaler, if the} \\ \text{prescaler is assigned to the WDT and} \\ \text{not Timer0. Status bits TO and PD are} \\ \text{set.} \\ 1 \end{array}$
Status Affected: Encoding: Description: Words: Cycles:	$\begin{array}{l} 0 \rightarrow \text{WDT prescaler (if assigned);} \\ 1 \rightarrow \overline{\text{TO};} \\ 1 \rightarrow \overline{\text{PD}} \\ \hline \overline{\text{TO}, \ \overline{\text{PD}}} \\ \hline \hline \hline 0000 & 0000 & 0100 \\ \hline \hline \\ \hline \text{De } CLRWDT \text{ instruction resets the } \\ WDT. It also resets the prescaler, if the prescaler is assigned to the WDT and not Timer0. Status bits TO and PD are set. \\ 1 \\ 1 \\ CLRWDT \\ \text{uction} \end{array}$



COMF	Complement f			
Syntax:	[ label ] COMF f,d			
Operands:	$0 \le f \le 31$ $d \in [0,1]$			
Operation:	$(\overline{f}) \rightarrow (dest)$			
Status Affected:	Z			
Encoding:	0010 01df ffff			
Description:	The contents of register 'f' are comple- mented. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'.			
Words:	1			
Cycles:	1			
Example:	COMF REG1,0			
Before Instru REG1	uction = 0x13			
After Instruc REG1 W	tion = 0x13 = 0xEC			

DECF	Decrement f			
Syntax:	[ <i>label</i> ] DECF f,d			
Operands:	$\begin{array}{l} 0 \leq f \leq 31 \\ d \in \ [0,1] \end{array}$			
Operation:	$(f) - 1 \rightarrow (dest)$			
Status Affected:	Z			
Encoding:	0000 11df ffff			
Description:	Decrement register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'.			
Words:	1			
Cycles:	1			
Example:	decf cnt, 1			
Before Instru CNT Z After Instruct CNT Z	= 0x01 = 0			

DECFSZ	Decrement f, Skip if 0			
Syntax:	[label] DECFSZ f,d			
Operands:	$0 \le f \le 31$ d \equiv [0,1]			
Operation:	(f) $-1 \rightarrow d$ ; skip if result = 0			
Status Affected:	None			
Encoding:	0010 11df ffff			
Description:	The contents of register 'f' are decre- mented. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f'. If the result is 0, the next instruction, which is already fetched, is discarded and an NOP is executed instead mak- ing it a two cycle instruction.			
Words:	1			
Cycles:	1(2)			
Example:	HERE DECFSZ CNT, 1 GOTO LOOP CONTINUE •			
	•			
Before Instru	iction			
PC	= address (HERE)			
After Instruct CNT if CNT PC if CNT PC	tion = CNT - 1; = 0, = address (CONTINUE); ≠ 0, = address (HERE+1)			
GOTO	Unconditional Branch			

GOTO	Unconditional Branch			
Syntax:	[ label ]	GOTO	k	
Operands:	$0 \le k \le 5^{\prime}$	11		
Operation:	$k \rightarrow$ PC<8:0>; STATUS<6:5> $\rightarrow$ PC<10:9>			
Status Affected:	None			
Encoding:	101k	kkkk	kkkk	
Description:	GOTO is an unconditional branch. The 9-bit immediate value is loaded into PC bits <8:0>. The upper bits of PC are loaded from STATUS<6:5>. GOTO is a two cycle instruction.			
Words:	1			
Cycles:	2			
Example:	GOTO THERE			
After Instruct PC =		(THERE)		



INCF	Increment f
Syntax:	[label] INCF f,d
Operands:	$0 \le f \le 31$ $d \in [0,1]$
Operation:	(f) + 1 $\rightarrow$ (dest)
Status Affected:	Z
Encoding:	0010 10df ffff
Description:	The contents of register 'f' are incre- mented. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f'.
Words:	1
Cycles:	1
Example:	INCF CNT, 1
Before Instru	
CNT Z	= 0xFF = 0
After Instruc	-
CNT Z	= 0x00 = 1
INCFSZ	Increment f, Skip if 0
Syntax:	[ <i>label</i> ] INCFSZ f,d
Operands:	$\begin{array}{l} 0 \leq f \leq 31 \\ d \in \left[0,1\right] \end{array}$
Operation:	(f) + 1 $\rightarrow$ (dest), skip if result = 0
Status Affected:	None
Encoding:	0011 11df ffff
Description:	The contents of register 'f' are incre- mented. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f'. If the result is 0, then the next instruc- tion, which is already fetched, is dis- carded and an NOP is executed instead making it a two cycle instruc- tion.
Words:	1
Cycles:	1(2)
Example:	HERE INCFSZ CNT, 1 GOTO LOOP CONTINUE •
	•
Before Instru PC	uction = address (HERE)

IORLW	Inclusive OR literal with W		
Syntax:	[ <i>label</i> ] IORLW k		
Operands:	$0 \le k \le 255$		
Operation:	(W) .OR. (k) $\rightarrow$ (W)		
Status Affected:	Z		
Encoding:	1101 kkkk kkkk		
Description:	The contents of the W register are OR'ed with the eight bit literal 'k'. The result is placed in the W register.		
Words:	1		
Cycles:	1		
Example:	IORLW 0x35		
Before Instru W =	iction 0x9A		
After Instruct W = Z =	tion 0xBF 0		
IORWF	Inclusive OR W with f		
Syntax:	[ <i>label</i> ] IORWF f,d		
Operands:	$\begin{array}{l} 0 \leq f \leq 31 \\ d \in \ [0,1] \end{array}$		
Operation:	(W).OR. (f) $\rightarrow$ (dest)		
Status Affected:	Z		
Encoding:	0001 00df ffff		
Description:	Inclusive OR the W register with regis- ter 'f'. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f'.		
Words:	1		
Cycles:	1		
Example:	IORWF RESULT, 0		
Before Instru RESULT W	= 0x13 = 0x91		
After Instruct RESULT W Z			

After Instruction CNT

if CNT

if CNT

PC

PC

=

=

=

CNT + 1;

address (CONTINUE);

address (HERE +1)

0, =

0, ≠

MOVF	Move f			
Syntax:	[ <i>label</i> ] MOVF f,d			
Operands:	$\begin{array}{l} 0 \leq f \leq 31 \\ d \in \ [0,1] \end{array}$			
Operation:	$(f) \rightarrow (dest)$			
Status Affected:	Z			
Encoding:	0010 00df ffff			
Description:	The contents of register 'f' is moved to destination 'd'. If 'd' is 0, destination is the W register. If 'd' is 1, the destination is file register 'f'. 'd' is 1 is useful to test a file register since status flag Z is affected.			
Words:	1			
Cycles:	1			
Example:	MOVF FSR, 0			
After Instruc W =	tion value in FSR register			

MOVLW	Move Literal to W
Syntax:	[ <i>label</i> ] MOVLW k
Operands:	$0 \le k \le 255$
Operation:	$k \rightarrow (W)$
Status Affected:	None
Encoding:	1100 kkkk kkkk
Description:	The eight bit literal 'k' is loaded into the W register. The don't cares will assemble as 0s.
Words:	1
Cycles:	1
Example:	MOVLW 0x5A
After Instruct W =	tion 0x5A

MOVWF	Move W	to f		
Syntax:	[ label ]	MOVWF	f	
Operands:	$0 \le f \le 3$	1		
Operation:	$(W) \rightarrow (1)$	f)		
Status Affected:	None			
Encoding:	0000	001f	ffff	
Description:	Move dat ter 'f'.	a from the	W register	to regis-
Words:	1			
Cycles:	1			
Example:	MOVWF	TEMP_REC	3	
Before Instru TEMP_R W		0xFF 0x4F		
After Instruct TEMP_R W		0x4F 0x4F		

NOP	No Operation			
Syntax:	[ label ]	NOP		
Operands:	None			
Operation:	No operation			
Status Affected:	None			
Encoding:	0000	0000	0000	
Description:	No operation.			
Words:	1			
Cycles:	1			
Example:	NOP			



OPTION	Load OPTION Register			
Syntax:	[ label ]	OPTION	1	
Operands:	None			
Operation:	$(W)\toO$	PTION		
Status Affected:	None			
Encoding:	0000	0000	0010	
Description:	The conte into the O		0	s loaded
Words:	1			
Cycles:	1			
Example	OPTION			
Before Instru W	iction = 0x07			
After Instruct OPTION				

RETLW	Return with	Literal in W
Syntax:	[label] RE	TLW k
Operands:	$0 \leq k \leq 255$	
Operation:	$\begin{array}{l} k \rightarrow (W);\\ TOS \rightarrow PC \end{array}$	
Status Affected:	None	
Encoding:	1000 kkl	kk kkkk
Description:	bit literal 'k'. Th loaded from the	is loaded with the eight e program counter is e top of the stack (the ). This is a two cycle
Words:	1	
Cycles:	2	
Example:	CALL TABLE •	;W contains ;table offset ;value. ;W now has table ;value.
TABLE	ADDWF PC RETLW k1 RETLW k2 RETLW kn	<pre>;W = offset ;Begin table ; ; ; End of table</pre>
Before Instru	iction	
W =	0x07	
After Instruct W =	tion value of k8	

RLF	Rotate Left f through Carry							
Syntax:	[ <i>label</i> ] RLF f,d							
Operands:	$\begin{array}{l} 0 \leq f \leq 31 \\ d \in \left[0,1\right] \end{array}$							
Operation:	See description below							
Status Affected:	С							
Encoding:	0011 01df ffff							
Description:	The contents of register 'f' are rotated one bit to the left through the Carry Flag. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is stored back in register 'f'.							
Words:	1							
Cycles:	1							
Example:	RLF REG1,0							
Before Instru REG1 C After Instruc REG1 W C	= 1110 0110 = 0							
RRF	Rotate Right f through Carry							
RRF Syntax:	Rotate Right f through Carry [ label ] RRF f,d							
Syntax:	[ <i>label</i> ] RRF f,d $0 \le f \le 31$							
Syntax: Operands:	[ <i>label</i> ] RRF f,d $0 \le f \le 31$ $d \in [0,1]$							
Syntax: Operands: Operation:	[ <i>label</i> ] RRF f,d $0 \le f \le 31$ $d \in [0,1]$ See description below							
Syntax: Operands: Operation: Status Affected:	$\begin{bmatrix} label \end{bmatrix} RRF f,d$ $0 \le f \le 31$ $d \in [0,1]$ See description below C $0011  00df  ffff$ The contents of register 'f' are rotated one bit to the right through the Carry Flag. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f'.							
Syntax: Operands: Operation: Status Affected: Encoding: Description:	$\begin{bmatrix} label \end{bmatrix} RRF f,d$ $0 \le f \le 31$ $d \in [0,1]$ See description below C $0011  00df  ffff$ The contents of register 'f' are rotated one bit to the right through the Carry Flag. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f'. $C = \frac{C}{C} = \frac{C}{C}$							
Syntax: Operands: Operation: Status Affected: Encoding: Description: Words:	[ <i>label</i> ] RRF f,d $0 \le f \le 31$ $d \in [0,1]$ See description below C 0011  00df  ffff The contents of register 'f' are rotated one bit to the right through the Carry Flag. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f'. C register 'f' 1							
Syntax: Operands: Operation: Status Affected: Encoding: Description: Words: Cycles:	[ <i>label</i> ] RRF f,d $0 \le f \le 31$ $d \in [0,1]$ See description below C 0011 00df ffff The contents of register 'f' are rotated one bit to the right through the Carry Flag. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f'. 1 1 1							
Syntax: Operands: Operation: Status Affected: Encoding: Description: Words: Cycles: Example:	[ <i>label</i> ] RRF f,d $0 \le f \le 31$ $d \in [0,1]$ See description below C 0011 00df ffff The contents of register 'f' are rotated one bit to the right through the Carry Flag. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f' 1 1 RRF REG1, 0							
Syntax: Operands: Operation: Status Affected: Encoding: Description: Words: Cycles:	[ <i>label</i> ] RRF f,d $0 \le f \le 31$ $d \in [0,1]$ See description below C 0011 00df ffff The contents of register 'f' are rotated one bit to the right through the Carry Flag. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f'. C register 'f' 1 1 RRF REG1, 0 uction = 1110 0110 = 0							



SLEEP	Enter SLEEP Mode							
Syntax:	[label]	SLEEP						
Operands:	None							
Operation:	$\begin{array}{l} 00h \rightarrow W \\ 0 \rightarrow WD \\ 1 \rightarrow \overline{TO}; \\ 0 \rightarrow \overline{PD} \end{array}$	/DT; F prescale	er;					
Status Affected:	TO, PD, O	GPWUF						
Encoding:	0000	0000	0011					
Description:	Time-out status bit (TO) is set. The power down status bit (PD) is cleared. GPWUF is unaffected. The WDT and its prescaler are cleared. The processor is put into SLEEP mode with the oscillator stopped. See sec- tion on SLEEP for more details.							
Words:	1							
Cycles:	1							
Example:	SLEEP							

SUBWF	Subtract W from f							
Syntax:	[labe	e/]	SUBWF	f,d				
Operands:	0 ≤ f d ∈ [	-						
Operation:	(f) –	(W)	$\rightarrow$ (dest)					
Status Affected:	C, D	C, Z						
Encoding:	000	0	10df	ffff				
Description:	W reg result	gister t is st	from regis	ment method) the ster 'f'. If 'd' is 0 the W register. If 'd' is back in register 'f'.				
Words:	1							
Cycles:	1							
Example 1:	SUBW	F	REG1, 1					
Example 1. Before Instruc REG1 W C After Instruc REG1 W C Example 2: Before Instruc REG1 W C After Instruc REG1 W C	iction = ; tion = ; = ; tion = ; tion = ;	3 2 ? 1 2 1 2 2 ? 0 2	; result is					
•	= '	1	; result is	zero				
Example 3:								
Before Instru REG1 W C	= 2	1 2 ?						
After Instruc REG1 W C	=	FF 2 0	; result is	negative				



SWAPF	Swap Nibbles in f								
Syntax:	[label] SWAPF f,d								
Operands:	$\begin{array}{l} 0 \leq f \leq 31 \\ d \in \ [0,1] \end{array}$								
Operation:	(f<3:0>) → (dest<7:4>); (f<7:4>) → (dest<3:0>)								
Status Affected:	None								
Encoding:	0011 10df ffff								
Description:	The upper and lower nibbles of register 'f' are exchanged. If 'd' is 0 the result is placed in W register. If 'd' is 1 the result is placed in register 'f'.								
Words:	1								
Cycles:	1								
Example	SWAPF REG1, 0								
Before Instru REG1	iction = 0xA5								
After Instruct									
REG1 W	= 0xA5 = 0X5A								
TRIS	Load TRIS Register								
Syntax:	[label] TRIS f								

11113	Load This hegister
Syntax:	[label] TRIS f
Operands:	f = 6
Operation:	(W) $\rightarrow$ TRIS register f
Status Affected:	None
Encoding:	0000 0000 0fff
Description:	TRIS register 'f' (f = 6) is loaded with the contents of the W register
Words:	1
Cycles:	1
Example	TRIS GPIO
Before Instr W	uction = 0XA5
After Instruc TRIS	ction = 0XA5
<b>Note:</b> f = 6	for PIC12C5XX only.

XORLW	Exclusive OR literal with W							
Syntax:	[ <i>label</i> ] XORLW k							
Operands:	$0 \le k \le 255$							
Operation:	(W) .XOR. $k \rightarrow (W)$							
Status Affected:	Z							
Encoding:	1111 kkkk kkkk							
Description:	The contents of the W register are XOR'ed with the eight bit literal 'k'. The result is placed in the W register.							
Words:	1							
Cycles:	1							
Example:	XORLW 0xAF							
Before Instru W =	uction 0xB5							
After Instruc W =	tion 0x1A							
XORWF	Exclusive OR W with f							
Syntax:	[label] XORWF f,d							
Operands:	$0 \le f \le 31$							

Ορε	erands:	$0 \le f \le 31$ d \equiv [0,1]								
Оре	eration:	(W) .XOR. (f) $\rightarrow$ (dest)								
Stat	us Affected:	Z								
Enc	oding:	0001	10df	ffff						
Des	cription:	register v result is s	OR the co vith register tored in the ult is stored	'f'. If 'd' is W registe	0 the r. If 'd' is					
Woi	ds:	1								
Сус	les:	1								
Exa	mple	XORWF	REG,1							
	Before Instru REG W After Instruct REG W	= 0xA = 0xB	5							



NOTES:



## 9.0 DEVELOPMENT SUPPORT

### 9.1 Development Tools

The PIC16/17 microcontrollers are supported with a full range of hardware and software development tools:

- PICMASTER/PICMASTER CE Real-Time In-Circuit Emulator
- ICEPIC Low-Cost PIC16C5X and PIC16CXXX In-Circuit Emulator
- PRO MATE<sup>®</sup> II Universal Programmer
- PICSTART<sup>®</sup> Plus Entry-Level Prototype Programmer
- PICDEM-1 Low-Cost Demonstration Board
- PICDEM-2 Low-Cost Demonstration Board
- PICDEM-3 Low-Cost Demonstration Board
- MPASM Assembler
- MPLAB-SIM Software Simulator
- MPLAB-C (C Compiler)
- Fuzzy logic development system (*fuzzy*TECH<sup>®</sup>–MP)

### 9.2 <u>PICMASTER: High Performance</u> <u>Universal In-Circuit Emulator with</u> <u>MPLAB IDE</u>

The PICMASTER Universal In-Circuit Emulator is intended to provide the product development engineer with a complete microcontroller design tool set for all microcontrollers in the PIC12C5XX, PIC14C000, PIC16C5X, PIC16CXXX and PIC17CXX families. PICMASTER is supplied with the MPLAB<sup>TM</sup> Integrated Development Environment (IDE), which allows editing, "make" and download, and source debugging from a single environment.

Interchangeable target probes allow the system to be easily reconfigured for emulation of different processors. The universal architecture of the PICMASTER allows expansion to support all new Microchip microcontrollers.

The PICMASTER Emulator System has been designed as a real-time emulation system with advanced features that are generally found on more expensive development tools. The PC compatible 386 (and higher) machine platform and Microsoft Windows<sup>®</sup> 3.x environment were chosen to best make these features available to you, the end user.

A CE compliant version of PICMASTER is available for European Union (EU) countries.

### 9.3 ICEPIC: Low-cost PIC16CXXX In-Circuit Emulator

ICEPIC is a low-cost in-circuit emulator solution for the Microchip PIC16C5X and PIC16CXXX families of 8-bit OTP microcontrollers.

ICEPIC is designed to operate on PC-compatible machines ranging from 286-AT<sup>®</sup> through Pentium<sup>™</sup> based machines under Windows 3.x environment. ICEPIC features real time, non-intrusive emulation.

## 9.4 PRO MATE II: Universal Programmer

The PRO MATE II Universal Programmer is a full-featured programmer capable of operating in stand-alone mode as well as PC-hosted mode.

The PRO MATE II has programmable VDD and VPP supplies which allows it to verify programmed memory at VDD min and VDD max for maximum reliability. It has an LCD display for displaying error messages, keys to enter commands and a modular detachable socket assembly to support various package types. In standalone mode the PRO MATE II can read, verify or program PIC16C5X, PIC16CXXX, PIC17CXX, PIC14000 and PIC12C5XX devices. It can also set configuration and code-protect bits in this mode.

## 9.5 <u>PICSTART Plus Entry Level</u> <u>Development System</u>

The PICSTART programmer is an easy-to-use, lowcost prototype programmer. It connects to the PC via one of the COM (RS-232) ports. MPLAB Integrated Development Environment software makes using the programmer simple and efficient. PICSTART Plus is not recommended for production programming.

PICSTART Plus supports all PIC12C5XX, PIC14000, PIC16C5X, PIC16CXXX and PIC17CXX devices with up to 40 pins. Larger pin count devices such as the PIC16C923 and PIC16C924 may be supported with an adapter socket.



#### 9.6 <u>PICDEM-1 Low-Cost PIC16/17</u> <u>Demonstration Board</u>

The PICDEM-1 is a simple board which demonstrates the capabilities of several of Microchip's microcontrollers. The microcontrollers supported are: PIC16C5X (PIC16C54 to PIC16C58A), PIC16C61, PIC16C62X, PIC16C71, PIC16C8X, PIC17C42, PIC17C43 and PIC17C44. All necessary hardware and software is included to run basic demo programs. The users can program the sample microcontrollers provided with the PICDEM-1 board, on a PRO MATE II or PICSTART-16B programmer, and easily test firmware. The user can also connect the PICDEM-1 board to the PICMASTER emulator and download the firmware to the emulator for testing. Additional prototype area is available for the user to build some additional hardware and connect it to the microcontroller socket(s). Some of the features include an RS-232 interface, a potentiometer for simulated analog input, push-button switches and eight LEDs connected to PORTB.

### 9.7 <u>PICDEM-2 Low-Cost PIC16CXX</u> Demonstration Board

The PICDEM-2 is a simple demonstration board that supports the PIC16C62, PIC16C64, PIC16C65, PIC16C73 and PIC16C74 microcontrollers. All the necessary hardware and software is included to run the basic demonstration programs. The user can program the sample microcontrollers provided with the PICDEM-2 board, on a PRO MATE II programmer or PICSTART-16C, and easily test firmware. The PICMASTER emulator may also be used with the PICDEM-2 board to test firmware. Additional prototype area has been provided to the user for adding additional hardware and connecting it to the microcontroller socket(s). Some of the features include a RS-232 interface, push-button switches, a potentiometer for simulated analog input, a Serial EEPROM to demonstrate usage of the I<sup>2</sup>C bus and separate headers for connection to an LCD module and a keypad.

### 9.8 PICDEM-3 Low-Cost PIC16CXXX Demonstration Board

The PICDEM-3 is a simple demonstration board that supports the PIC16C923 and PIC16C924 in the PLCC package. It will also support future 44-pin PLCC microcontrollers with a LCD Module. All the necessary hardware and software is included to run the basic demonstration programs. The user can program the sample microcontrollers provided with the PICDEM-3 board, on a PRO MATE II programmer or PICSTART Plus with an adapter socket, and easily test firmware. The PICMASTER emulator may also be used with the PICDEM-3 board to test firmware. Additional prototype area has been provided to the user for adding hardware and connecting it to the microcontroller socket(s). Some of the features include an RS-232 interface, push-button switches, a potentiometer for simulated analog input, a thermistor and separate headers for connection to an external LCD module and a keypad. Also provided on the PICDEM-3 board is an LCD panel, with 4 commons and 12 segments, that is capable of displaying time, temperature and day of the week. The PICDEM-3 provides an additional RS-232 interface and Windows 3.1 software for showing the demultiplexed LCD signals on a PC. A simple serial interface allows the user to construct a hardware demultiplexer for the LCD signals.

## 9.9 <u>MPLAB Integrated Development</u> <u>Environment Software</u>

The MPLAB IDE Software brings an ease of software development previously unseen in the 8-bit microcontroller market. MPLAB is a windows based application which contains:

- A full featured editor
- Three operating modes
  - editor
  - emulator
  - simulator
- A project manager
- Customizable tool bar and key mapping
- A status bar with project information

Extensive on-line help

MPLAB allows you to:

- Edit your source files (either assembly or 'C')
- One touch assemble (or compile) and download to PIC16/17 tools (automatically updates all project information)
- Debug using:
- source files
- absolute listing file
- Transfer data dynamically via DDE (soon to be replaced by OLE)
- Run up to four emulators on the same PC

The ability to use MPLAB with Microchip's simulator allows a consistent platform and the ability to easily switch from the low cost simulator to the full featured emulator with minimal retraining due to development tools.

#### 9.10 Assembler (MPASM)

The MPASM Universal Macro Assembler is a PChosted symbolic assembler. It supports all microcontroller series including the PIC12C5XX, PIC14000, PIC16C5X, PIC16CXXX, and PIC17CXX families.

MPASM offers full featured Macro capabilities, conditional assembly, and several source and listing formats. It generates various object code formats to support Microchip's development tools as well as third party programmers.

MPASM allows full symbolic debugging from PICMASTER, Microchip's Universal Emulator System.

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MPASM has the following features to assist in developing software for specific use applications.

- Provides translation of Assembler source code to object code for all Microchip microcontrollers.
- Macro assembly capability.
- Produces all the files (Object, Listing, Symbol, and special) required for symbolic debug with Microchip's emulator systems.
- Supports Hex (default), Decimal and Octal source and listing formats.

MPASM provides a rich directive language to support programming of the PIC16/17. Directives are helpful in making the development of your assemble source code shorter and more maintainable.

## 9.11 Software Simulator (MPLAB-SIM)

The MPLAB-SIM Software Simulator allows code development in a PC host environment. It allows the user to simulate the PIC16/17 series microcontrollers on an instruction level. On any given instruction, the user may examine or modify any of the data areas or provide external stimulus to any of the pins. The input/ output radix can be set by the user and the execution can be performed in; single step, execute until break, or in a trace mode.

MPLAB-SIM fully supports symbolic debugging using MPLAB-C and MPASM. The Software Simulator offers the low cost flexibility to develop and debug code outside of the laboratory environment making it an excellent multi-project software development tool.

## 9.12 <u>C Compiler (MPLAB-C)</u>

The MPLAB-C Code Development System is a complete 'C' compiler and integrated development environment for Microchip's PIC16/17 family of micro-controllers. The compiler provides powerful integration capabilities and ease of use not found with other compilers.

For easier source level debugging, the compiler provides symbol information that is compatible with the MPLAB IDE memory display (PICMASTER emulator software versions 1.13 and later).

### 9.13 <u>Fuzzy Logic Development System</u> (*fuzzy*TECH-MP)

*fuzzy*TECH-MP fuzzy logic development tool is available in two versions - a low cost introductory version, MP Explorer, for designers to gain a comprehensive working knowledge of fuzzy logic system design; and a full-featured version, *fuzzy*TECH-MP, edition for implementing more complex systems.

Both versions include Microchip's *fuzzy*LAB<sup>™</sup> demonstration board for hands-on experience with fuzzy logic systems implementation.

### 9.14 <u>MP-DriveWay™ – Application Code</u> <u>Generator</u>

MP-DriveWay is an easy-to-use Windows-based Application Code Generator. With MP-DriveWay you can visually configure all the peripherals in a PIC16/17 device and, with a click of the mouse, generate all the initialization and many functional code modules in C language. The output is fully compatible with Microchip's MPLAB-C C compiler. The code produced is highly modular and allows easy integration of your own code. MP-DriveWay is intelligent enough to maintain your code through subsequent code generation.

## 9.15 <u>SEEVAL<sup>®</sup> Evaluation and</u> <u>Programming System</u>

The SEEVAL SEEPROM Designer's Kit supports all Microchip 2-wire and 3-wire Serial EEPROMs. The kit includes everything necessary to read, write, erase or program special features of any Microchip SEEPROM product including Smart Serials<sup>™</sup> and secure serials. The Total Endurance<sup>™</sup> Disk is included to aid in trade-off analysis and reliability calculations. The total kit can significantly reduce time-to-market and result in an optimized system.

## 9.16 <u>KEELOQ<sup>®</sup> Evaluation and</u> <u>Programming Tools</u>

KEELOQ evaluation and programming tools support Microchips HCS Secure Data Products. The HCS evaluation kit includes an LCD display to show changing codes, a decoder to decode transmissions, and a programming interface to program test transmitters.



## TABLE 9-1: DEVELOPMENT TOOLS FROM MICROCHIP

X HCS200 X HCS300 X HCS301										2	2					2
24CXX 25CXX 93CXX							7			7		7				
PIC17C75X	Available 3Q97		7	2					7	7						
PIC17C4X	7		7	7	7	7			2	7			7			
PIC16C9XX	>		7	2	7				7	7					7	
PIC16C8X	>	7	2	7	7	2		7	7	7			7			
PIC16C7XX	2	7	7	7	7	2		7	7	7				7		
PIC16C6X	2	7	7	7	7	7		7	7	7				7		
PIC16CXXX	7	7	2	7	7	7			7	7			7			
PIC16C5X	7	7	7	7	7	2		7	7	7			7			
PIC14000	7		7	2	7				7	7						
PIC12C5XX	>	7	>	7	7				7	7						
	PICMASTER®/ PICMASTER-CE In-Circuit Emulator	ICEPIC Low-Cost In-Circuit Emulator	MPLAB™ Integrated Development Environment	MPLAB™ C Compiler	<i>fuzz</i> yTECH®-MP Explorer/Edition Fuzzy Logic Dev. Tool	MP-DriveWay™ Applications Code Generator	Total Endurance™ Software Model	PICSTART <sup>®</sup> Lite Ultra Low-Cost Dev. Kit	PICSTART <sup>®</sup> Plus Low-Cost Universal Dev. Kit	PRO MATE <sup>®</sup> II Universal Programmer	KEELOQ <sup>®</sup> Programmer	SEEVAL <sup>®</sup> Designers Kit	PICDEM-1	PICDEM-2	PICDEM-3	KEELOQ <sup>®</sup> Evaluation Kit
	roducts	Emulator P		slo	oT <del>siswiio</del> č				ammers	Progr			spie	0 B 0	oməC	1

# 10.0 ELECTRICAL CHARACTERISTICS - PIC12C5XX

## Absolute Maximum Ratings†

Ambient Temperature under bias	–40°C to +125°C
Storage Temperature	–65°C to +150°C
Voltage on VDD with respect to Vss	
Voltage on MCLR with respect to Vss	0 to +14 V
Voltage on all other pins with respect to Vss	
Total Power Dissipation <sup>(1)</sup>	700 mW
Max. Current out of Vss pin	200 mA
Max. Current into VDD pin	150 mA
Input Clamp Current, Iiк (Vi < 0 or Vi > VDD)	±20 mA
Output Clamp Current, IOK (VO < 0 or VO > VDD)	±20 mA
Max. Output Current sunk by any I/O pin	25 mA
Max. Output Current sourced by any I/O pin	25 mA
Max. Output Current sourced by I/O port (GPIO)	100 mA
Max. Output Current sunk by I/O port (GPIO )	100 mA
<b>Note 1:</b> Power Dissipation is calculated as follows: PDIS = VDD x {IDD - $\Sigma$ IOH} + $\Sigma$ {(VDD-VDD) x {IDD - $\Sigma$ IOH} + $\Sigma$ {(VDD-VD) x {IDD - $\Sigma$ IDD x {IDD	/OH) X IOH} + $\Sigma$ (VOL X IOL)

<sup>†</sup>NOTICE: Stresses above those listed under "Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.



### 10.1 DC CHARACTERISTICS:

#### PIC12508/509 (Commercial) PIC12508/509 (Industrial) PIC12508/509 (Extended)

DC Characteristics Power Supply Pins		Standard Operating Conditions (unless otherwise specified)Operating Temperature $0^{\circ}C \le TA \le +70^{\circ}C$ (commercial) $-40^{\circ}C \le TA \le +85^{\circ}C$ (industrial) $-40^{\circ}C \le TA \le +125^{\circ}C$ (extended)					
Characteristic	Sym	Min	Тур <sup>(1)</sup>	Max	Units	Conditions	
Supply Voltage	Vdd	2.5		5.5	V	Fosc = DC to 4 MHz (Commercial/ Industrial)	
		3.0		5.5	V	Fosc = DC to 4 MHz (Extended)	
RAM Data Retention Voltage <sup>(2)</sup>	Vdr		1.5*		V	Device in SLEEP mode	
VDD Start Voltage to ensure Power-on Reset	VPOR		Vss		V	See section on Power-on Reset for details	
VDD Rise Rate to ensure Power-on Reset	SVDD	0.05*			V/ms	See section on Power-on Reset for details	
Supply Current <sup>(3)</sup>	IDD	-	1.8	2.4	mA	XT and EXTRC options (Note 4) Fosc = 4 MHz, VDD = 5.5V	
		-	1.8	2.4	mA	INTRC Option Fosc = 4 MHz, VDD = 5.5V	
		-	15	27	μA	LP OPTION, Commercial Temperature Fosc = 32 kHz, VDD = 3.0V, WDT disabled	
		-	19	35	μA	LP OPTION, Industrial Temperature Fosc = 32 kHz, VDD = 3.0V, WDT disabled	
		-	19	35	μA	LP OPTION, Extended Temperature Fosc = 32 kHz, VDD = 3.0V, WDT disabled	
Power-Down Current <sup>(5)</sup>	IPD						
WDT Enabled		-	4	12	μA	VDD = 3.0V, Commercial	
			4	14	μA	VDD = 3.0V, Industrial	
		-	5	22	μA	VDD = 3.0V, Extended	
WDT Disabled		-	0.25	4	μA	VDD = 3.0V, Commercial	
			0.25 2	5 18	μΑ μΑ	VDD = 3.0V, Industrial VDD = 3.0V, Extended	

\* These parameters are characterized but not tested.

- Note 1: Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.
  - 2: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.
  - 3: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern, and temperature also have an impact on the current consumption.
    - a) The test conditions for all IDD measurements in active operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to
      - $V_{ss}$ , TOCKI = VDD,  $\overline{MCLR}$  = VDD; WDT enabled/disabled as specified.
    - b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode.
  - 4: Does not include current through Rext. The current through the resistor can be estimated by the formula: IR = VDD/2Rext (mA) with Rext in kOhm.
  - 5: The power down current in SLEEP mode does not depend on the oscillator type. Power down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or Vss.



## 10.2 DC CHARACTERISTICS:

### PIC12508/509 (Commercial) PIC12508/509 (Industrial) PIC12508/509 (Extended)

DC Characteristics All Pins Except Power Supply Pins		$\begin{array}{ll} \mbox{Standard Operating Conditions (unless otherwise specified)} \\ \mbox{Operating Temperature} & 0^{\circ}C \leq TA \leq +70^{\circ}C \mbox{ (commercial)} \\ & -40^{\circ}C \leq TA \leq +85^{\circ}C \mbox{ (industrial)} \\ & -40^{\circ}C \leq TA \leq +125^{\circ}C \mbox{ (extended)} \\ \mbox{Operating Voltage VDD range is described in Section 10.1.} \end{array}$									
Characteristic	Sym	Min Typ <sup>(1)</sup> Max Units Conditions									
Input Low Voltage I/O ports	VIL	Vss Vss		0.8 0.15 Vdd	V V	Pin at hi-impedance $4.5V < VDD \le 5.5V$ Pin at hi-impedance					
MCLR and GP2 (Schmitt Trigger) OSC1 OSC1		Vss Vss Vss		0.15 VDD 0.15 VDD 0.3 VDD	V V V	$3.0V < VDD \le 4.5V$ EXTRC option only <sup>(4)</sup> XT and LP options					
Input High Voltage I/O ports	Vih	0.25VDD+0.8V 2.0 0.2VDD+1V 0.85 VDD 0.85 VDD		VDD VDD VDD VDD VDD	V V V V	$2.5V < VDD \le 4.5V$ $4.5V < VDD \le 5.5V^{(5)}$ Full VDD range <sup>(5)</sup> EXTRC option only <sup>(4)</sup>					
OSC1 (Schmitt Trigger)		0.85 VDD 0.7 VDD		VDD VDD	V	XT and LP options					
Input Leakage Current <sup>(2,3)</sup> I/O ports	lι∟	-1	0.5	+1	μΑ	For VDD $\leq$ 5.5V VSS $\leq$ VPIN $\leq$ VDD, Pin at hi-impedance					
MCLR		20	130 0.5	250 +5	μΑ μΑ	$VPIN = VSS + 0.25V^{(2)}$ VPIN = VDD					
OSC1		-3	0.5	+3	μA	$\label{eq:VSS} \begin{array}{l} VSS \leq VPIN \leq VDD, \\ XT \text{ and } LP \text{ options} \end{array}$					
Output Low Voltage I/O ports	Vol			0.6	V	IOL = 8.7 mA, VDD = 4.5V					
Output High Voltage <sup>(3,4)</sup> I/O ports	VoH	Vdd -0.7			V	IOH = -5.4 mA, VDD = 4.5V					

\* These parameters are characterized but not tested.

Note 1: Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

2: The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltage.

3: Negative current is defined as coming out of the pin.

4: For PIC12C5XX devices, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC12C5XX be driven with external clock in RC mode.

5: The user may use the better of the two specifications.



## 10.3 Timing Parameter Symbology and Load Conditions

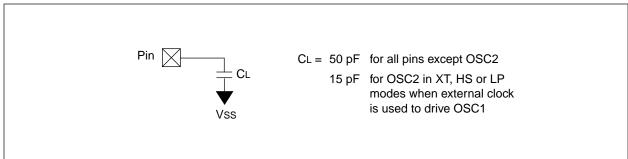
The timing parameter symbols have been created following one of the following formats:

1. TppS2ppS

2. TppS

2. Tpp3			
т			
F	Frequency	Т	Time
Lowerd	case subscripts (pp) and their meanings:		
рр			
2	to	mc	MCLR
ck	CLKOUT	osc	oscillator
су	cycle time	os	OSC1
drt	device reset timer	tO	TOCKI
io	I/O port	wdt	watchdog timer
Upperc	case letters and their meanings:		
S			
F	Fall	P	Period
Н	High	R	Rise
I	Invalid (Hi-impedance)	V	Valid
L	Low	Z	Hi-impedance

## FIGURE 10-1: LOAD CONDITIONS - PIC12C5XX





## 10.4 Timing Diagrams and Specifications

# FIGURE 10-2: EXTERNAL CLOCK TIMING - PIC12C5XX Q4 Q1 Q2 Q3 Q4 Q1 OSC1 Q4 Q1 Q2 Q3 Q4 Q1 43 + 44 + 44

TABLE 10-1:	<b>EXTERNAL CLOCK TIMING REQUIREMENTS - PIC12C5XX</b>

AC Characteristics		$\begin{array}{lll} \mbox{Standard Operating Conditions (unless otherwise specified)} \\ \mbox{Operating Temperature} & 0^{\circ}C \leq TA \leq +70^{\circ}C \ (commercial), \\ & -40^{\circ}C \leq TA \leq +85^{\circ}C \ (industrial), \\ & -40^{\circ}C \leq TA \leq +125^{\circ}C \ (extended) \\ \mbox{Operating Voltage VDD range is described in Section 10.1} \end{array}$					
Parameter No.	Sym	Characteristic	Min	Typ <sup>(1)</sup>	Max	Units	Conditions
	Fosc	External CLKIN Frequency <sup>(2)</sup>	DC	—	4	MHz	EXTRC osc mode
			DC	-	4	MHz	XT osc mode
			DC	—	200	kHz	LP osc mode
		Oscillator Frequency <sup>(2)</sup>	DC	—	4	MHz	EXTRC osc mode
			0.1	_	4	MHz	XT osc mode
			DC		200	kHz	LP osc mode
1	Tosc	External CLKIN Period <sup>(2)</sup>	250	_		ns	EXTRC osc mode
			250	-	—	ns	XT osc mode
			5	—	—	ms	LP osc mode
		Oscillator Period <sup>(2)</sup>	250	_		ns	EXTRC osc mode
			250	_	10,000	ns	XT osc mode
			5		_	ms	LP osc mode
2	Тсу	Instruction Cycle Time <sup>(3)</sup>	-	4/Fosc	—	_	
3	TosL, TosH	Clock in (OSC1) Low or High Time	50*	_	_	ns	XT oscillator
			2*	_	—	ms	LP oscillator
4	TosR, TosF	Clock in (OSC1) Rise or Fall Time	-	—	25*	ns	XT oscillator
			_		50*	ns	LP oscillator

\* These parameters are characterized but not tested.

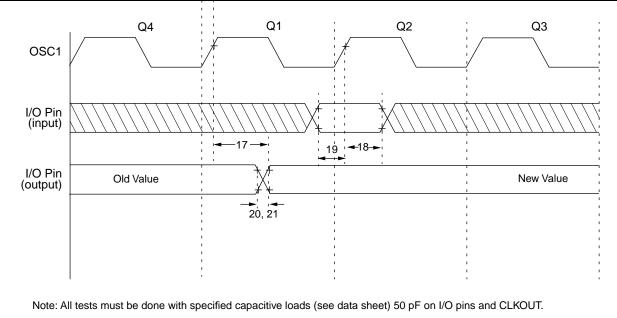
Note 1: Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

2: All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

Instruction cycle period (TCY) equals four times the input oscillator time base period.



## FIGURE 10-3: I/O TIMING - PIC12C5XX



## TABLE 10-2:TIMING REQUIREMENTS - PIC12C5XX

AC Chara	cteristics	$-40^{\circ}C \le TA \le$	+70°C (comme +85°C (industri +125°C (extend	rcial) al) ded)	)	
Parameter No.	Sym	Characteristic	Min	Typ <sup>(1)</sup>	Max	Units
17	TosH2ioV	OSC1 <sup>↑</sup> (Q1 cycle) to Port out valid <sup>(3)</sup>	—	-	100*	ns
18	TosH2iol	OSC1 <sup>↑</sup> (Q2 cycle) to Port input invalid (I/O in hold time)	TBD	—	—	ns
19	TioV2osH	Port input valid to OSC1 <sup>↑</sup> (I/O in setup time)	TBD	—	_	ns
20	TioR	Port output rise time <sup>(3)</sup>	—	10	25**	ns
21	TioF	Port output fall time <sup>(3)</sup>	—	10	25**	ns

\* These parameters are characterized but not tested.

\*\* These parameters are design targets and are not tested. No characterization data available at this time.

Note 1: Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

2: Measurements are taken in EXTRC mode.

3: See Figure 10-1 for loading conditions.



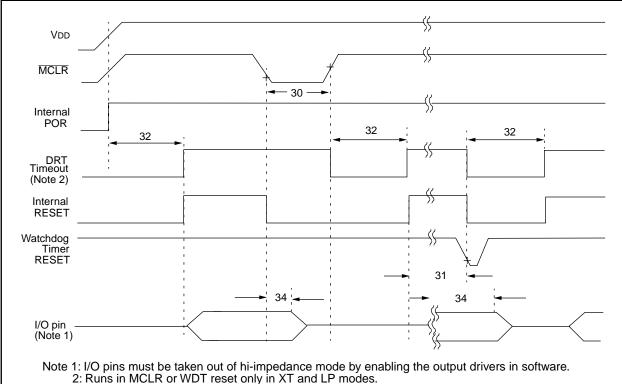


FIGURE 10-4: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER TIMING - PIC12C5XX

#### TABLE 10-3: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER - PIC12C5XX

AC Characteristics		$ \begin{array}{ll} \mbox{Standard Operating Conditions (unless otherwise specified)} \\ \mbox{Operating Temperature} & 0^\circ C \leq T A \leq +70^\circ C \mbox{ (commercial)} \\ & -40^\circ C \leq T A \leq +85^\circ C \mbox{ (industrial)} \\ & -40^\circ C \leq T A \leq +125^\circ C \mbox{ (extended)} \\ \mbox{Operating Voltage VDD range is described in Section 10.1} \end{array} $						
Parameter No.	Sym	Characteristic	Min	Typ <sup>(1)</sup>	Мах	Units	Conditions	
30	TmcL	MCLR Pulse Width (low)	2000*		_	ns	VDD = 5 V	
31	Twdt	Watchdog Timer Time-out Period (No Prescaler)	9*	18*	30*	ms	VDD = 5 V (Commercial)	
32	Tdrt	Device Reset Timer Period <sup>(2)</sup>	9*	18*	30*	ms	VDD = 5 V (Commercial)	
34 Tioz		I/O Hi-impedance from MCLR Low			2000*	ns		

\* These parameters are characterized but not tested.

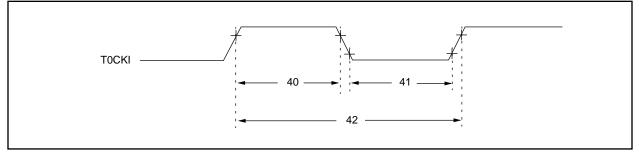
Note 1: Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

#### TABLE 10-4: DRT (DEVICE RESET TIMER PERIOD)

Oscillator Configuration	POR Reset	Subsequent Resets		
IntRC & ExtRC	18 ms (typical)	300 μs (typical)		
XT & LP	18 ms (typical)	18 ms (typical)		



## FIGURE 10-5: TIMER0 CLOCK TIMINGS - PIC12C5XX



### TABLE 10-5: TIMER0 CLOCK REQUIREMENTS - PIC12C5XX

AC Characteristics			Standard Operating Conditions (unless otherwise specified)Operating Temperature $0^{\circ}C \le TA \le +70^{\circ}C$ (commercial) $-40^{\circ}C \le TA \le +85^{\circ}C$ (industrial) $-40^{\circ}C \le TA \le +125^{\circ}C$ (extended)Operating Voltage VDD range is described in Section 10.1.					
Parameter No. Sym Characteristic				Min	Typ <sup>(1)</sup>	Max	Units	Conditions
40	Tt0H	T0CKI High Pulse V	Vidth - No Prescaler	0.5 TCY + 20*	_		ns	
			- With Prescaler	10*	_	_	ns	
41	Tt0L	T0CKI Low Pulse V	/idth - No Prescaler	0.5 TCY + 20*	—	_	ns	
			- With Prescaler	10*	—		ns	
42	Tt0P	T0CKI Period		20 or <u>Tcy + 40</u> * N		_	ns	Whichever is greater. N = Prescale Value (1, 2, 4,, 256)

\* These parameters are characterized but not tested.

Note 1: Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

### TABLE 10-6: PULL-UP RESISTOR RANGES

VDD (Volts)	Temperature (°C)	Min	Тур	Max	Units
		GP0/	/GP1		
2.5	-40	50K	62K	84K	Ω
	25	63K	73K	84K	Ω
	85	63K	80K	84K	Ω
	125	63K	81K	84K	Ω
5.5	-40	19K	22K	27K	Ω
	25	25K	27K	31K	Ω
	85	28K	33K	40K	Ω
	125	31K	36K	43K	Ω
		GI	P3		
2.5	-40	490K	710K	965K	Ω
	25	610K	890K	1.2M	Ω
	85	769K	1.1M	1.5M	Ω
	125	810K	1.2M	1.6M	Ω
5.5	-40	310K	410K	510K	Ω
	25	360K	470K	580K	Ω
	85	430K	550K	670K	Ω
	125	465K	585K	715K	Ω

\* These parameters are characterized but not tested.

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# 11.0 DC AND AC CHARACTERISTICS - PIC12C5XX

The graphs and tables provided in this section are for design guidance and are not tested or guaranteed. In some graphs or tables the data presented are outside specified operating range (e.g., outside specified VbD range). This is for information only and devices will operate properly only within the specified range.

The data presented in this section is a statistical summary of data collected on units from different lots over a period of time. "Typical" represents the mean of the distribution while "max" or "min" represents (mean +  $3\sigma$ ) and (mean -  $3\sigma$ ) respectively, where  $\sigma$  is standard deviation.

### FIGURE 11-1: CALIBRATED INTERNAL RC FREQUENCY RANGE VS. TEMPERATURE (VDD = 5.0V) (INTERNAL RC IS CALIBRATED TO 25°C, 5.0V)

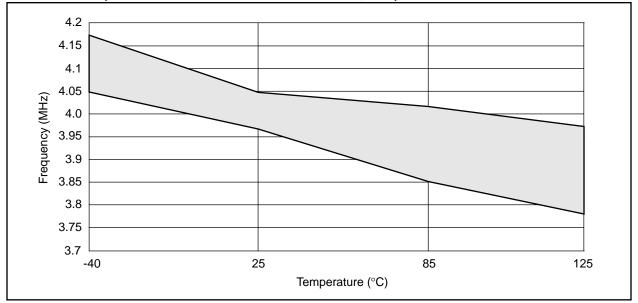
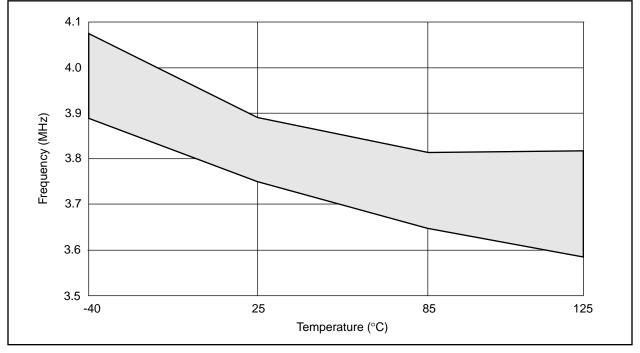


FIGURE 11-2: CALIBRATED INTERNAL RC FREQUENCY RANGE VS. TEMPERATURE (VDD = 3.0V) (INTERNAL RC IS CALIBRATED TO 25°C, 5.0V)



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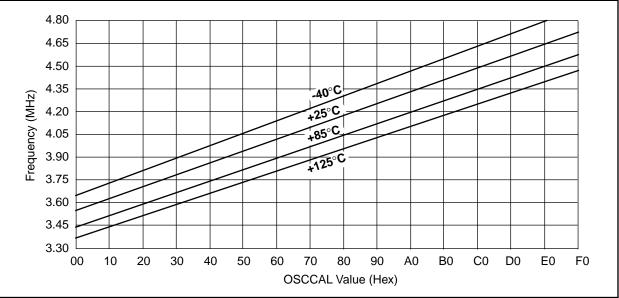
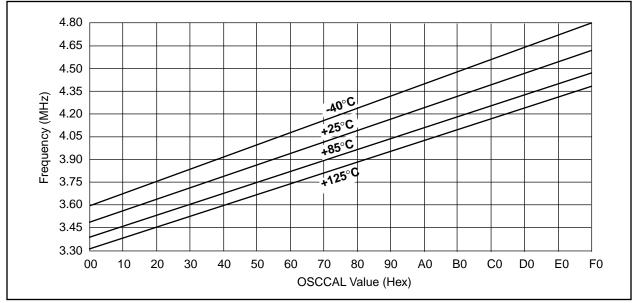


FIGURE 11-4: INTERNAL RC FREQUENCY VS. CALIBRATION VALUE (VDD = 3.5V)

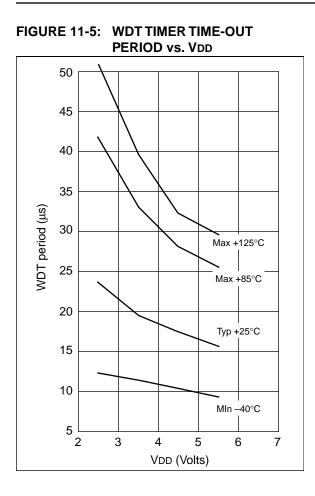


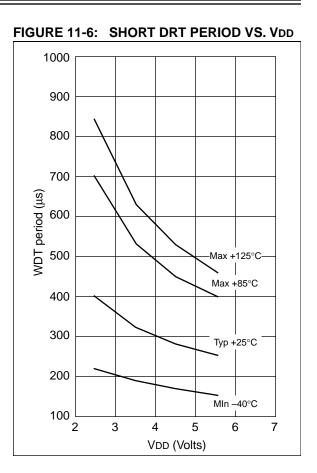


Oscillator	Frequency	VDD = 2.5V	VDD = 5.5V
External RC	4 MHz	250 μA*	620 μA*
Internal RC	4 MHz	420 μA	1.1 mA
XT	4 MHz	251 μA	775 μA
LP	32 KHz	7 μΑ	37 μΑ

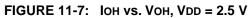
\*Does not include current through external R&C.

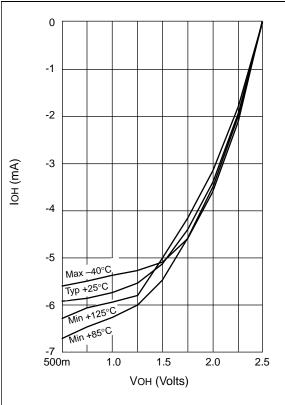


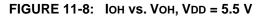


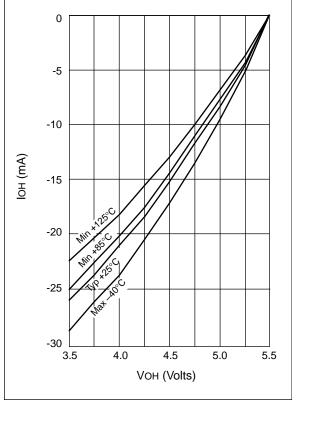


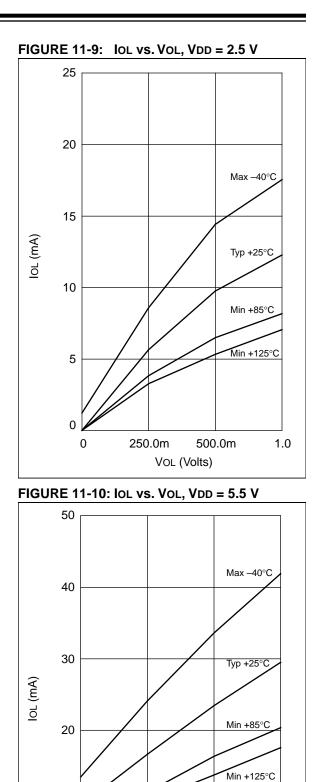












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10

0

250.0m

500.0m

750.0m

VOL (Volts)

1.0

# 12.0 PACKAGING INFORMATION

## 12.1 Package Marking Information



MMMMMMMM XXXXXCDE XABB

### 8-Lead SOIC (208 mil)



Example	
12C508/P 04ISAZ <b>XX</b> 9625	

## Example

•	
12C508 04I/SM 9624SAZ	

## 8-Lead Windowed Ceramic Side Brazed (300 mil)





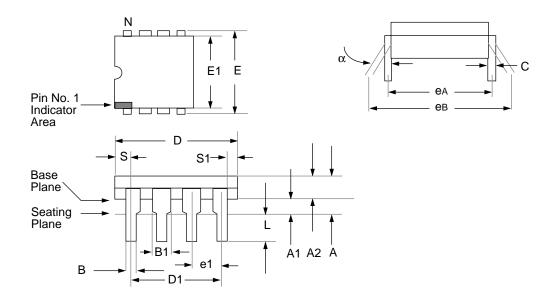


Legend	d: MMM	Microchip part number information
	XXX	Customer specific information*
	AA	Year code (last 2 digits of calendar year)
	BB	Week code (week of January 1 is week '01')
	С	Facility code of the plant at which wafer is manufactured
		C = Chandler, Arizona, U.S.A.,
		S = Tempe, Arizona, U.S.A.
	D	Mask revision number
	E	Assembly code of the plant or country of origin in which
		part was assembled
Note:	In the ever	nt the full Microchip part number cannot be marked on one line,
	it will be c	arried over to the next line thus limiting the number of available
	characters	s for customer specific information.
* Sta	andard OTF	marking consists of Microchip part number, year code, week
CO	de. facility	code, mask rev#, and assembly code. For OTP marking

Standard OTP marking consists of Microchip part number, year code, week code, facility code, mask rev#, and assembly code. For OTP marking beyond this, certain price adders apply. Please check with your Microchip Sales Office. For QTP devices, any special marking adders are included in QTP price.



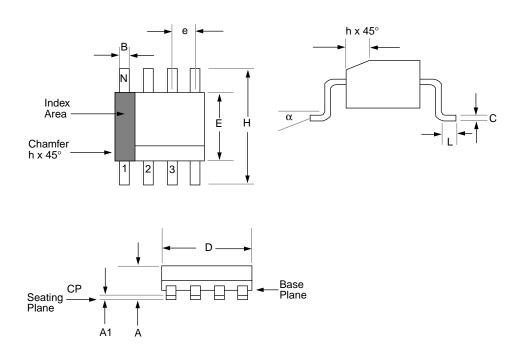
## 12.2 8-Lead Plastic Dual In-line (300 mil)



	Package Group: Plastic Dual In-Line (PLA)						
		Millimeters					
Symbol	Min	Max	Notes	Min	Max	Notes	
α	0°	10°		0°	10°		
А	_	4.064		_	0.160		
A1	0.381	_		0.015	_		
A2	3.048	3.810		0.120	0.150		
В	0.355	0.559		0.014	0.022		
B1	1.397	1.651		0.055 0.065			
С	0.203	0.381	Typical	0.008	0.015	Typical	
D	9.017	10.922		0.355	0.430		
D1	7.620	7.620	Reference	0.300	0.300	Reference	
E	7.620	8.255		0.300	0.325		
E1	6.096	7.112		0.240	0.280		
e1	2.489	2.591	Typical	0.098	0.102	Typical	
eA	7.620	7.620	Reference	0.300	0.300	Reference	
eB	7.874	9.906		0.310	0.390		
L	3.048	3.556		0.120	0.140		
Ν	8	8		8	8		
S	0.889	_		0.035	_		
S1	0.254	_		0.010	_		



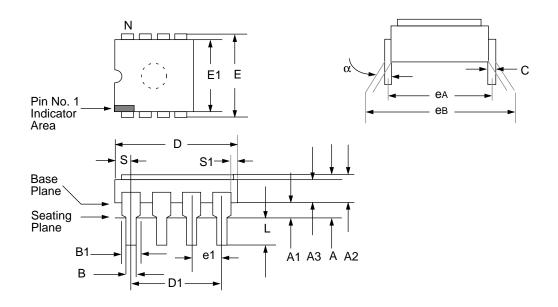
## 12.3 8-Lead Plastic Surface Mount (SOIC - Medium, 208 mil Body)



	Package Group: Plastic SOIC (SM)					
	Millimeters					
Symbol	Min	Max	Notes	Min	Мах	Notes
α	0°	8°		0°	8°	
А	1.778	2.00		0.070	0.079	
A1	0.101	0.249		0.004	0.010	
В	0.355	0.483		0.014 0.019		
С	0.190	0.249		0.007 0.010		
D	5.080	5.334		0.200 0.210		
E	5.156	5.411		0.203 0.213		
е	1.270	1.270	Reference	0.050	0.050	Reference
H*	7.670	8.103		0.302	0.319	
h	0.381	0.762		0.015	0.030	
L	0.508	1.016		0.020	0.040	
Ν	14	14		14	14	
CP	_	0.102		_	0.004	



## 12.4 8-Lead Ceramic Side Brazed Dual In-Line with Window (JW) (300 mil)



Package Group: Ceramic Side Brazed Dual In-Line (CER)							
Cumhal		Millimeters	In		Inches		
Symbol	Min	Max	Notes	Min	Max	Notes	
α	0°	10°		0°	10°		
А	3.937	5.030		0.155	0.198		
A1	0.635	1.143		0.025	0.045		
A2	2.921	3.429		0.115	0.135		
A3	1.778	2.413		0.070	0.095		
В	0.406	0.508		0.016	0.020		
B1	1.371	1.371	Typical	0.054	0.054	Typical	
С	0.228	0.305	Typical	0.009	0.012	Typical	
D	13.004	13.412		0.512	0.528		
D1	7.416	7.824	BSC	0.292	0.308	BSC	
E	7.569	8.230		0.298	0.324		
E1	7.112	7.620		0.280	0.300		
e1	2.540	2.540	Typical	0.100	0.100	Typical	
eA	7.620	7.620	BSC	0.300	0.300	BSC	
eB	7.620	9.652		0.300	0.380		
L	3.302	4.064		0.130	0.160		
S	2.540	3.048		0.100	0.120		
S1	0.127	_		0.005	_		



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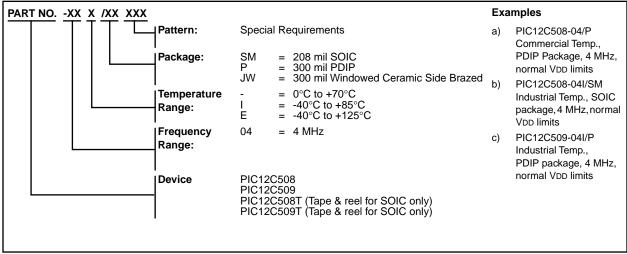
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6	Is there any incorrect or mislead	ing information (what and where)?
0.		
7.	How would you improve this doc	ument?
8.	How would you improve our soft	ware, systems, and silicon products?

## PIC12C5XX PRODUCT IDENTIFICATION SYSTEM



Please contact your local sales office for exact ordering procedures.

### Sales and Support

Products supported by a preliminary Data Sheet may possibly have an errata sheet describing minor operational differences and recommended workarounds. To determine if an errata sheet exists for a particular device, please contact one of the following:

- 1. Your local Microchip sales office (see below)
- 2. The Microchip Corporate Literature Center U.S. FAX: (602) 786-7277
- 3. The Microchip's Bulletin Board, via your local CompuServe number (CompuServe membership NOT required).

Please specify which device, revision of silicon and Data Sheet (include Literature #) you are using.

For latest version information and upgrade kits for Microchip Development Tools, please call 1-800-755-2345 or 1-602-786-7302.

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